

# **M72** Hardware Design

**GSM/GPRS Module Series**

Rev. M72\_Hardware\_Design\_V4.1

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# About the Document

## History

Revision	Date	Author	Description
1.0	2011-02-22	Crystal HE	Initial
1.1	2011-08-22	Layne YE	<ol style="list-style-type: none"> <li>1. Modified current consumption value from 0.9mA to 1.1mA in SLEEP mode when DRX is 5.</li> <li>2. Added supported internet service protocols, e.g. MMS, SMTP, HTTP.</li> <li>3. Added Figure 32 for antenna interface reference circuit.</li> <li>4. Modified the storage temperature value from 90°C to 85°C in Table 22.</li> </ol>
3.0	2012-03-05	Baly BAO	<ol style="list-style-type: none"> <li>1. Modified the operating voltage range to 3.3V~4.6V.</li> <li>2. Modified the maximum peak current to 1.8A.</li> <li>3. Hardware flow control is disabled by default.</li> </ol>
3.1	2012-03-31	Baly BAO	MMS and SMTP are not supported.
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7. Modified the current consumption information in Section 5.3 & 5.4
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# 1 Introduction

This document defines M72 module and describes the hardware interface of M72 module that connects to the customer application and the air interface.

This document can help you quickly understand module interface specifications, electrical and mechanical details. Associated with software application notes and user guide, you can use M72 module to design and set up mobile applications easily.

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## 1.1. Safety Information

The following safety precautions must be observed during all phases of the operation, such as usage, service or repair of any cellular terminal or mobile incorporating M72 module. Manufacturers of the cellular terminal should send the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. If not so, Quectel does not take on any liability for your failure to comply with these precautions.



Full attention must be given to driving at all times in order to reduce the risk of an accident. Using a mobile while driving (even with a handsfree kit) cause distraction and can lead to an accident. You must comply with laws and regulations restricting the use of wireless devices while driving.



Switch off the cellular terminal or mobile before boarding an aircraft. Make sure it switched off. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communication systems. Consult the airline staff about the use of wireless devices on boarding the aircraft. If your device offers a Flight Mode which must be enabled prior to boarding an aircraft.



Switch off your wireless device when in hospitals or clinics or other health care facilities. These requests are designed to prevent possible interference with sensitive medical equipment.



Cellular terminals or mobiles operate over radio frequency signal and cellular network and cannot be guaranteed to connect in all conditions, for example no mobile fee or an invalid SIM card. While you are in this condition and need emergent help, please remember using emergency call. In order to make or receive call, the cellular terminal or mobile must be switched on and in a service area with adequate cellular signal strength.



Your cellular terminal or mobile contains a transmitter and receiver. When it is ON, it receives and transmits radio frequency energy. RF interference can occur if it is used close to TV set, radio, computer or other electric equipment.



In locations with potentially explosive atmospheres, obey all posted signs to turn off wireless devices such as your phone or other cellular terminals. Areas with potentially explosive atmospheres including fuelling areas, below decks on boats, fuel or chemical transfer or storage facilities, areas where the air contains chemicals or particles such as grain, dust or metal powders.

## 2 Product Concept

### 2.1. General Description

M72 is a Dual-band GSM/GPRS engine that works at frequencies of EGSM900MHz and DCS1800MHz. M72 features GPRS multi-slot class 12 and supports the GPRS coding schemes CS-1, CS-2, CS-3 and CS-4. For more details about GPRS multi-slot classes and coding schemes, please refer to **Appendix B&C**.

With a tiny profile of 27.5mm × 24.0mm × 2.7mm, the module can meet almost all the requirements for data transfer applications.

M72 is an SMD type module, which can be embedded in customer's application through its 30-pin pads. Furthermore, it provides abundant hardware interfaces.

The module is designed with power saving techniques so that the current consumption is as low as 1.3mA in SLEEP mode when DRX is 5.

M72 is integrated with protocols which are TCP/UDP, FTP, PPP, HTTP, etc. Extended AT commands have been developed for customers to use these Internet service protocols easily.

The modules are fully RoHS compliant to EU regulation.

### 2.2. Key Features

The following table describes the detailed features of M72 module.

**Table 1: Module Key Features**

Feature	Implementation
Power Supply	Single supply voltage: 3.3V~4.6V Typical supply voltage: 4V
Power Saving	Typical power consumption in SLEEP mode: 1.3mA @DRX=5 1.2mA @DRX=9

Frequency Bands	<ul style="list-style-type: none"> <li>● Dual-band: EGSM900, DCS1800</li> <li>● The module can search these frequency bands automatically</li> <li>● The frequency bands can be set by AT command</li> <li>● Compliant to GSM Phase 2/2+</li> </ul>
Transmitting Power	<ul style="list-style-type: none"> <li>● Class 4 (2W) at EGSM900</li> <li>● Class 1 (1W) at DCS1800</li> </ul>
GPRS Connectivity	<ul style="list-style-type: none"> <li>● GPRS multi-slot class 12 (default)</li> <li>● GPRS multi-slot class 1~12 (configurable)</li> <li>● GPRS mobile station class B</li> </ul>
Temperature Range	<ul style="list-style-type: none"> <li>● Normal operation: -35°C ~ +80°C</li> <li>● Restricted operation: -40°C ~ -35°C and +80°C ~ +85°C <sup>1)</sup></li> <li>● Storage temperature: -45°C ~ +90°C</li> </ul>
DATA GPRS	<ul style="list-style-type: none"> <li>● GPRS data downlink transfer: max. 85.6kbps</li> <li>● GPRS data uplink transfer: max. 85.6kbps</li> <li>● Coding scheme: CS-1, CS-2, CS-3 and CS-4</li> <li>● Support the protocols PAP (Password Authentication Protocol) usually used for PPP connections</li> <li>● Internet service protocols TCP/UDP, FTP, PPP, HTTP, etc.</li> <li>● Support Unstructured Supplementary Service Data (USSD)</li> </ul>
SMS	<ul style="list-style-type: none"> <li>● MT, MO, CB, Text and PDU mode</li> <li>● SMS storage: SIM card</li> </ul>
SIM Interface	Support SIM card: 1.8V/3.0V
Antenna Interface	Connected via 50ohm antenna pad
Alarm Function	Programmable via AT command
Physical Characteristics	Size: 27.5±0.15 × 24.0±0.15 × 2.7±0.2mm Weight: Approx. 3.3g
Firmware Upgrade	Firmware upgrade via UART Port

**NOTE**

<sup>1)</sup>When the module works within this temperature range, the deviations from the GSM specification may occur. For example, the frequency error or the phase error will be increased.

**Table 2: Coding Schemes and Maximum Net Data Rates over Air Interface**

Coding Scheme	1 Timeslot	2 Timeslot	4 Timeslot
CS-1	9.05kbps	18.1kbps	36.2kbps

CS-2	13.4kbps	26.8kbps	53.6kbps
CS-3	15.6kbps	31.2kbps	62.4kbps
CS-4	21.4kbps	42.8kbps	85.6kbps

### 2.3. Functional Diagram

The following figure shows a block diagram of M72 and illustrates the major functional parts.

- Power management
- Baseband
- The GSM radio frequency part
- The peripheral interface
  - Power supply
  - Turn-on/off interface
  - UART interfaces
  - SIM interface
  - RTC interface
  - RF interface

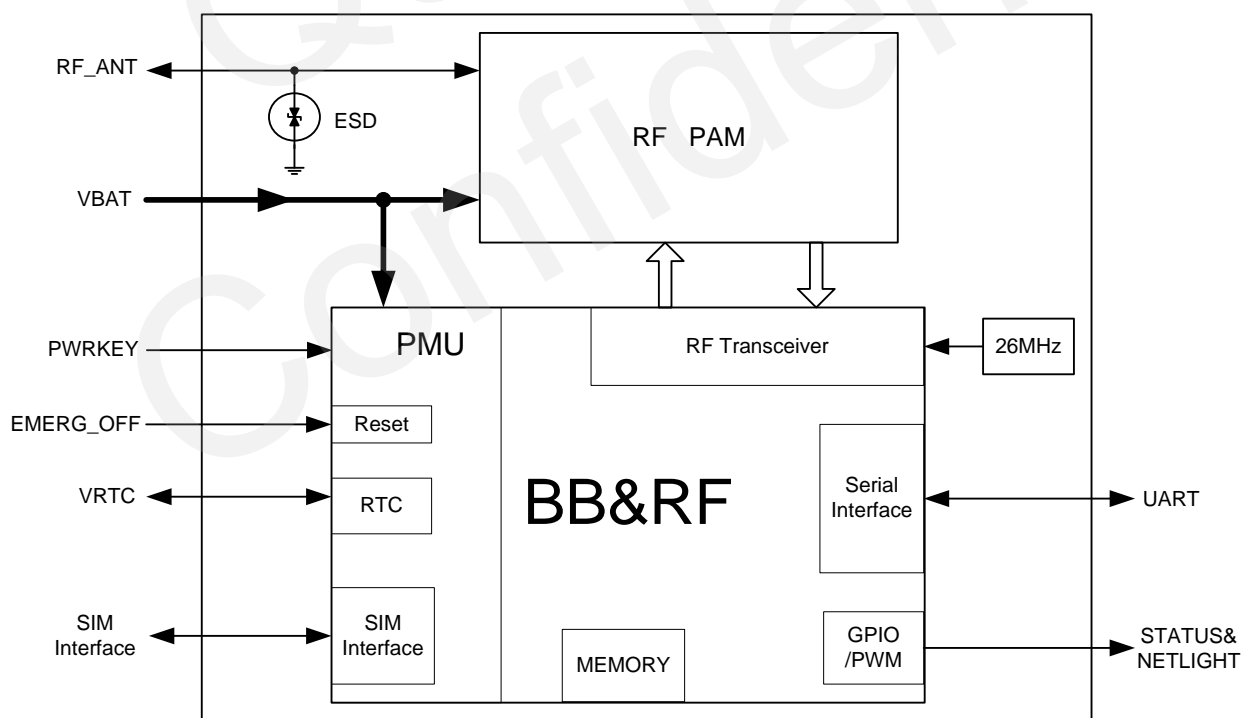


Figure 1: Module Functional Diagram

## 2.4. Evaluation Board

In order to help customers with the application of M72, Quectel supplies an Evaluation Board (EVB) that hosts the module directly with appropriate power supply, earphone, RS-232 serial interface, antenna and other peripherals to control or test the module. For details, please refer to the **document [4]**.

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## 3 Application Interface

The module is equipped with a 30-pin 1.1mm pitch SMT pad that connects to the cellular application platform. Sub-interfaces included in these pads are described in details in the following chapters:

- Power supply
- Power on/down
- Power saving
- RTC
- Serial interfaces
- SIM interface
- RI
- NETLIGHT
- STATUS

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### 3.1. Pin of Modules

#### 3.1.1. Pin Assignment

The following figure shows the pin assignment and interface definition of M72.

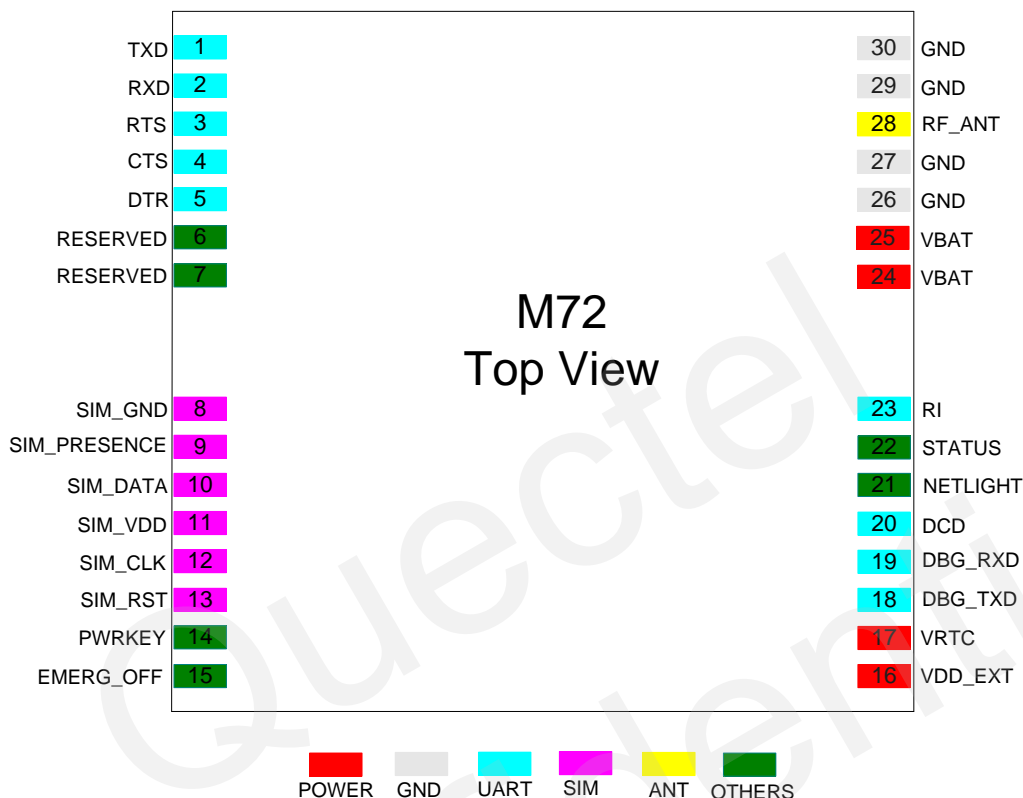


Figure 2: Pin Assignment of M72

#### 3.1.2. Pin Description

Table 3: Pin Description

Power Supply						
PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT	
VBAT	24, 25	I	Main power supply of module: VBAT=3.3V~4.6V	Vmax=4.6V Vmin=3.3V Vnorm=4.0V	Make sure that supply sufficient current in a transmitting burst typically rises to 1.6A.	



VRTC	17	I/O	Power supply for RTC when VBAT is not supplied for the system. Charging for backup battery or a large-capacitance capacitor when the VBAT is applied.	$V_{I\max}=3.3V$ $V_{I\min}=1.5V$ $V_{Inorm}=2.8V$ $V_{O\max}=3V$ $V_{O\min}=2V$ $V_{Onorm}=2.8V$ $I_{out(max)}=2mA$ $I_{in}\approx 10\mu A$	Recommended to be connected to a backup battery or a large-capacitance capacitor. If unused, keep this pin open.
VDD_EXT	16	O	Supply 2.8V voltage for external circuit.	$V_{\max}=2.9V$ $V_{\min}=2.7V$ $V_{norm}=2.8V$ $I_{\max}=20mA$	If unused, keep this pin open. Recommend to add a 2.2~4.7uF bypass capacitor, when using this pin for power supply.
GND	26, 27, 29, 30		Ground		

**Power on or Power off**

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
PWRKEY	14	I	Power on/off pin. PWRKEY should be pulled down for a moment to turn on or turn off the system.	$V_{IL\max}=0.1\times V_{BAT}$ $V_{IH\min}=0.6\times V_{BAT}$ $V_{I\max}=3.1V$	

**Emergency Shutdown**

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
EMERG_OFF	15	I	Emergency off. Pulled down for at least 40ms, which will turn off the module in case of emergency. Use it only when shutdown via PWRKEY or AT command cannot be achieved.	$V_{IL\max}=0.45V$ $V_{IH\min}=1.35V$ $V_{open\max}=1.8V$	Open drain/collector driver required in cellular device application. If unused, keep this pin open.

**Module Status Indication**

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
----------	---------	-----	-------------	--------------------	---------

STATUS	22	O	Indicate module's operating status. Output high level when module turns on, while output low level when module turns off.	VOHmin= 0.85×VDD_EXT VOLmax= 0.15×VDD_EXT	If unused, keep this pin open.
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**Network Status Indicator**

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
NETLIGHT	21	O	Network status indication	VOHmin= 0.85×VDD_EXT VOLmax= 0.15×VDD_EXT	If unused, keep this pin open.

**UART Port/Debug Port**

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
DTR	5	I	Data terminal ready	VILmin=0V	
RXD	2	I	Receive data	VILmax= 0.25×VDD_EXT	If only use TXD, RXD and GND to communicate, it is recommended to connect RTS to GND via 0R resistor and keeping other pins open.
TXD	1	O	Transmit data	VIHmin= 0.75×VDD_EXT	
RTS	3	I	Request to send	VIHmax= VDD_EXT+0.2	
CTS	4	O	Clear to send	VOHmin= 0.85×VDD_EXT	
RI	23	O	Ring indication	VOLmax= 0.15×VDD_EXT	
DCD	20	O	Data carrier detection		
DBG_TXD	18	O	Transmit data for debugging only	Same as above	If unused, keep these pins open.
DBG_RXD	19	I	Receive data for debugging only		

**SIM Interface**

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
SIM_VDD	11	O	Power supply for SIM card	The voltage can be selected by software automatically. Either 1.8V or 3V.	All signals of SIM interface should be protected against ESD with a TVS diode array. Maximum trace length is 200mm
SIM_CLK	12	O	SIM clock	VOLmax= 0.15×SIM_VDD VOHmin=	

				0.85×SIM_VDD	from the module pad to SIM card holder.
SIM_DATA	10	I/O	SIM data	VILmax= 0.25×SIM_VDD VIHmin= 0.75×SIM_VDD VOLmax= 0.15×SIM_VDD VOHmin= 0.85×SIM_VDD	
SIM_RST	13	O	SIM reset	VOLmax= 0.15×SIM_VDD VOHmin= 0.85×SIM_VDD	
SIM_PRESENCE	9	I	SIM card detection	VILmin=0V VILmax= 0.25×VDD_EXT VIHmin= 0.75×VDD_EXT VIHmax= VDD_EXT+0.2	If unused, keep this pin open.
SIM_GND	8		SIM ground		

#### RF Interface

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
RF_ANT	28	I/O	RF antenna pad	Impedance of 50Ω	Refer to <b>Chapter 4</b>

#### Reserved Pins

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
RESERVED	6, 7				Keep these pins open

## 3.2. Operating Modes

The table below briefly summarizes the various operating modes in the following chapters.

**Table 4: Overview of Operating Modes**

Mode	Function
Normal Operation	GSM/GPRS Sleep After enabling sleep mode by <b>AT+QSCLK=1</b> , the module will automatically go into Sleep Mode if DTR is set to high level and there is no interrupt (such as GPIO interrupt or data on UART port). In this case, the current consumption of module will reduce to the minimal level. During Sleep Mode, the module can still receive paging message and SMS from the system normally.
	GSM IDLE Software is active. The module has registered to the GSM network, and the module is ready to send and receive GSM data.
	GPRS IDLE The module is not registered to GPRS network. The module is not reachable through GPRS channel.
	GPRS STANDBY The module is registered to GPRS network, but no GPRS PDP context is active. The SGSN knows the Routing Area where the module is located at.
	GPRS READY The PDP context is active, but no data transfer is ongoing. The module is ready to receive or send GPRS data. The SGSN knows the cell where the module is located at.
	GPRS DATA There is GPRS data in transfer. In this mode, power consumption is decided by the PCL, working RF band and GPRS multi-slot configuration.
POWER DOWN Normal shutdown by sending the “ <b>AT+QPOWD=1</b> ” command, using the PWRKEY or the EMERG_OFF <sup>1)</sup> pin. The power management ASIC disconnects the power supply from the base band part of the module, and only the power supply for the RTC is remained. Software is not active. The serial interfaces are not accessible. Operating voltage (connected to VBAT) remains applied.	
Minimum Functionality Mode (without removing power supply) “ <b>AT+CFUN</b> ” command can set the module to a minimum functionality mode without removing the power supply. In this case, the RF part of the module will not work or the SIM card will not be accessible, or both RF part and SIM card will be disabled, but the UART port is still accessible. The power consumption in this case is very low.	

**NOTE**

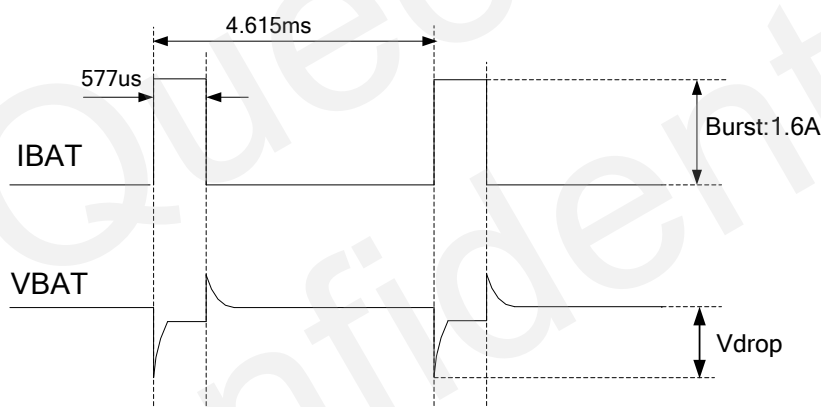
<sup>1)</sup> Use the EMERG\_OFF pin only when failing to turn off the module by the command “AT+QPOWD=1” and the PWRKEY pin. For more details, please refer to the **Section 3.4.2.4**.

### 3.3. Power Supply

#### 3.3.1. Power Features of Module

The power supply is one of the key issues in designing GSM terminals. Because of the 577us radio burst in GSM every 4.615 ms, power supply must be able to deliver high current peaks in a burst period. During these peaks, drops on the supply voltage must not exceed minimum working voltage of module.

For the M72 module, the max current consumption could reach to 1.6A during a transmit burst. It will cause a large voltage drop on the VBAT. In order to ensure stable operation of the module, it is recommended that the max voltage drop during the transmit burst does not exceed 400mV.



**Figure 3: Voltage Ripple during Transmitting**

#### 3.3.2. Decrease Supply Voltage Drop

The power supply range of the module is 3.3V to 4.6V. Make sure that the input voltage will never drop below 3.3V even in a transmitting burst. If the power voltage drops below 3.3V, the module could turn off automatically. For better power performance, it is recommended to place a 100uF tantalum capacitor with low ESR (ESR=0.7Ω) and ceramic capacitor 100nF, 33pF and 10pF near the VBAT pin. The reference circuit is illustrated in Figure 4.

The VBAT route should be wide enough to ensure that there is not too much voltage drop during transmit burst. The width of trace should be no less than 2mm and the principle of the VBAT route is the longer route, the wider trace.

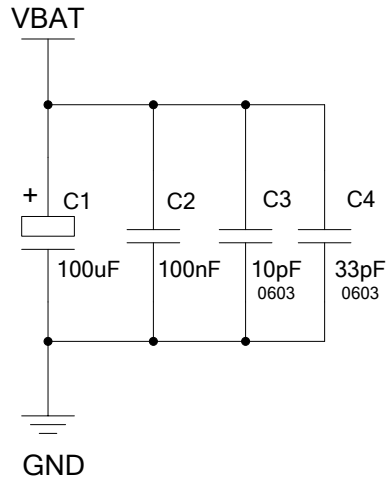


Figure 4: Reference Circuit for the VBAT Input

### 3.3.3. Reference Design for Power Supply

The power design for the module is very important, since the performance of power supply for the module largely depends on the power source. The power supply is capable of providing the sufficient current up to 2A at least. If the voltage drop between the input and output is not too high, it is suggested to use a LDO as module's power supply. If there is a big voltage difference between the input source and the desired output (VBAT), a switcher power converter is recommended to use as a power supply.

Figure 5 shows a reference design for +5V input power source. The designed output for the power supply is 4.0V and the maximum load current is 3A. In addition, in order to get a stable output voltage, a zener diode is placed close to the pins of VBAT. As to the zener diode, it is suggested to use a zener diode whose reverse zener voltage is 5.1V and dissipation power is more than 1 Watt.

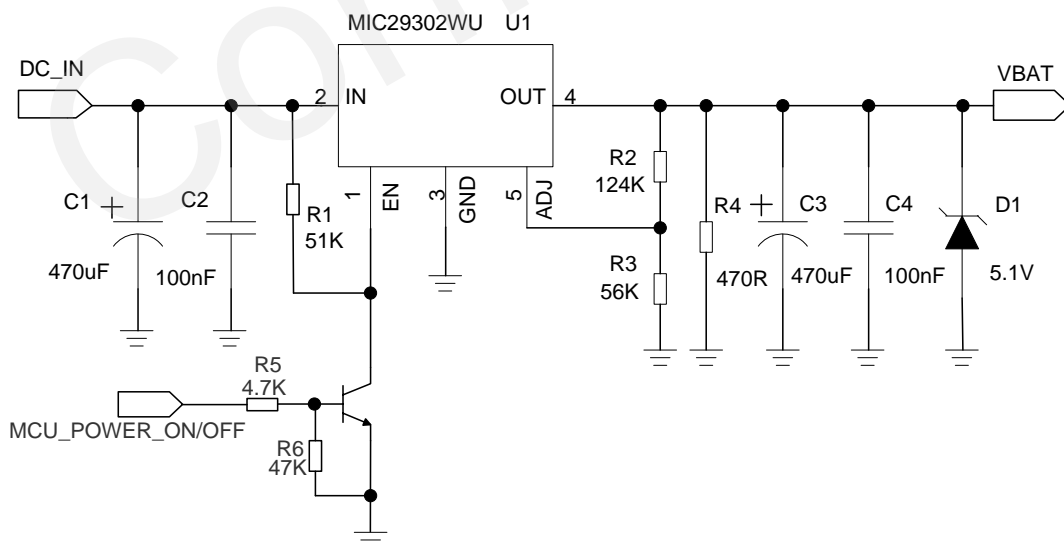


Figure 5: Reference Circuit for Power Supply

**NOTE**

It is suggested to control the module's main power supply (VBAT) via LDO enable pin to restart the module when the module has become abnormal. Power switch circuit like P-channel MOSFET switch circuit can also be used to control VBAT.

### 3.3.4. Monitor Power Supply

The command “**AT+CBC**” can be used to monitor the supply voltage of the module. The unit of the displayed voltage is mV.

For details, please refer to the **document [1]**.

## 3.4. Power On and Down Scenarios

### 3.4.1. Power On Module Using PWRKEY Pin

The module can be turned on by driving the pin PWRKEY to a low level voltage. An open collector driver circuit is suggested to control the PWRKEY. A simple reference circuit is illustrated as below.

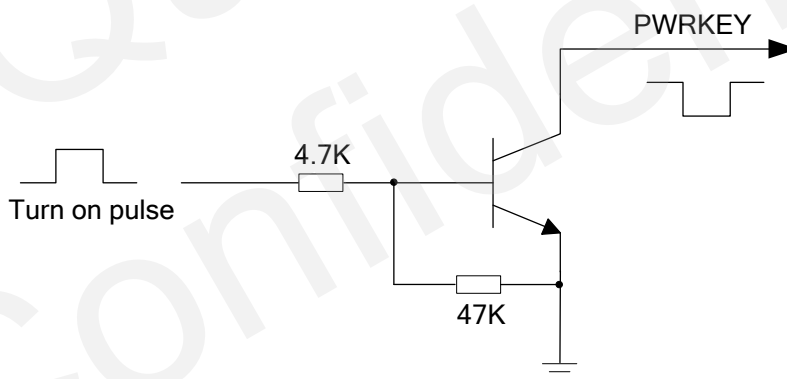


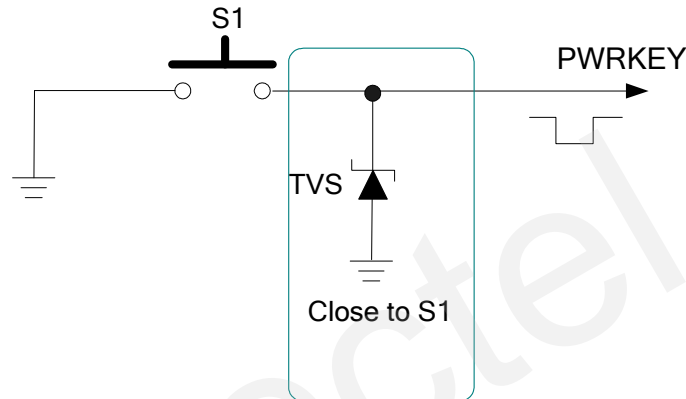
Figure 6: Reference Design for Driving the PWRKEY Pin

**NOTE**

M72 module is set to autobauding mode (**AT+IPR=0**) by default. In the autobauding mode, URC “RDY” is not reported to the host controller after module is powered on. When the module is powered on after a delay of 4 or 5 seconds, it can receive AT command. Host controller should first send an “AT” for the module to detect baud rate of host controller, and it should continue to send the next “AT” string until receiving “OK” string from the module. Then enter “**AT+IPR=x;&W**” to set a fixed baud rate for the module

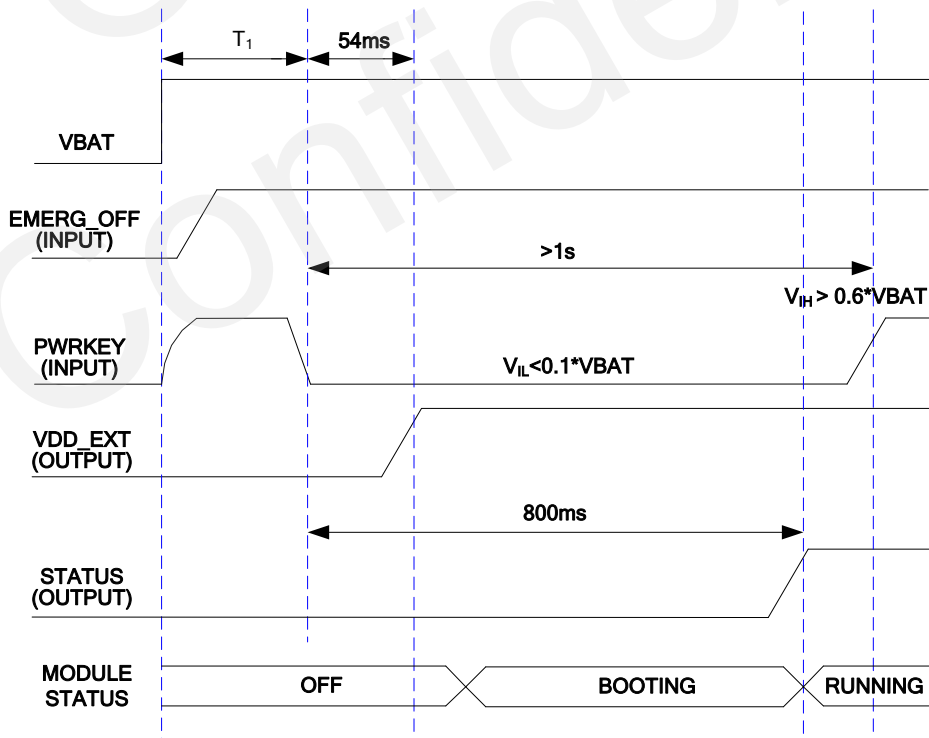
and save the configuration to flash memory of the module. After these configurations, the URC “RDY” would be received from the UART port of the module every time when the module is powered on. For more details, refer to the section “AT+IPR” in **document [1]**.

The other way to control the PWRKEY is through a button directly. A TVS component is indispensable to be placed nearby the button for ESD protection. For the best performance, the TVS component must be placed nearby the button. When pressing the key, electrostatic strike may generate from finger. A reference circuit is shown in the following figure.



**Figure 7: Reference Design for the PWRKEY with a Button**

The turn-on timing is illustrated as the following figure.



**Figure 8: Turn-on Timing**



**NOTES**

1. Make sure that VBAT is stable before pulling down PWRKEY pin. The time of  $T_1$  is recommended as 100ms.
2. EMERG\_OFF should be floated when it is unused.
3. For more details about the application of STATUS pin, please refer to the **Chapter 3.11**.

### 3.4.2. Power Down

The following procedures can be used to turn off the module:

- Normal power down procedure: Turn off module using the PWRKEY pin.
- Normal power down procedure: Turn off module using command “AT+QPOWD=1”.
- Over-voltage or under-voltage automatic shutdown: Take effect when over-voltage or under-voltage is detected.
- Emergent power down procedure: Turn off module using the EMERG\_OFF pin.

Thereafter, no further AT commands can be executed. Then the module enters the POWER DOWN mode and only the RTC is still active. The POWER DOWN mode can also be indicated by the STATUS pin, which is a low voltage level in this mode.

#### 3.4.2.1. Power Down Module Using the PWRKEY Pin

It is a safe way to turn off the module by driving the PWRKEY to a low level voltage for a certain time. The power down scenario is illustrated as below.

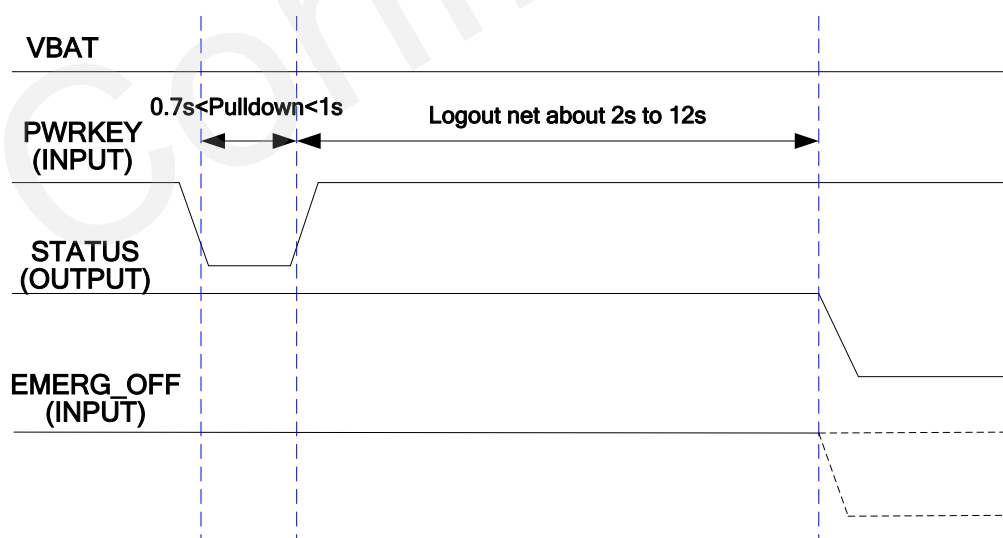


Figure 9: Turn-off Timing

The power down procedure causes the module to log off from the network and allows the firmware to save important data before completely disconnecting the power supply.

Before the completion of the power down procedure, the module sends the result code as shown below:

### ***NORMAL POWER DOWN***

#### **NOTES**

1. This unsolicited result codes do not appear when autobauding is active and DTE and DCE are not correctly synchronized after start-up. The module is recommended to set to a fixed baud rate.
2. As logout network time is related to the local mobile network, it is recommended to delay about 12 seconds before disconnecting the power supply or restarting the module.
3. For more details about the application of STATUS pin, please refer to the **Chapter 3.11**.

#### **3.4.2.2.Power Down Module Using AT Command**

It is also a safe way to turn off the module via AT command “**AT+QPOWD=1**”. This command will let the module log off from the network and allow the firmware to save important data before completely disconnecting the power supply.

Before the completion of the power down procedure the module sends the result code as shown below:

### ***NORMAL POWER DOWN***

Please refer to the **document [1]** for details about the AT command “**AT+QPOWD**”.

#### **3.4.2.3.Over-voltage or Under-voltage Automatic Shutdown**

The module will constantly monitor the voltage applied on the VBAT, if the voltage is  $\leq 3.5V$ , the following URC will be presented:

### ***UNDER\_VOLTAGE WARNING***

If the voltage is  $\geq 4.5V$ , the following URC will be presented:

### ***OVER\_VOLTAGE WARNING***

The normal input voltage range is from 3.3V to 4.6V. If the voltage is  $> 4.6V$  or  $< 3.3V$ , the module would automatically shut down itself.

If the voltage is  $< 3.3V$ , the following URC will be presented:

**UNDER\_VOLTAGE POWER DOWN**

If the voltage is  $> 4.6V$ , the following URC will be presented:

**OVER\_VOLTAGE POWER DOWN**

#### NOTES

1. These unsolicited result codes do not appear when autobauding is active and DTE and DCE are not correctly synchronized after start-up. The module is recommended to set to a fixed baud rate.
2. Over-voltage warning and shutdown function is disabled by default.

#### 3.4.2.4. Emergency Shutdown Using EMERG\_OFF Pin

The module can be shut down by driving the pin EMERG\_OFF to a low level voltage over 40ms and then releasing it. The EMERG\_OFF line can be driven by an open-drain/collector driver or a button. The circuit is illustrated as the following figures.

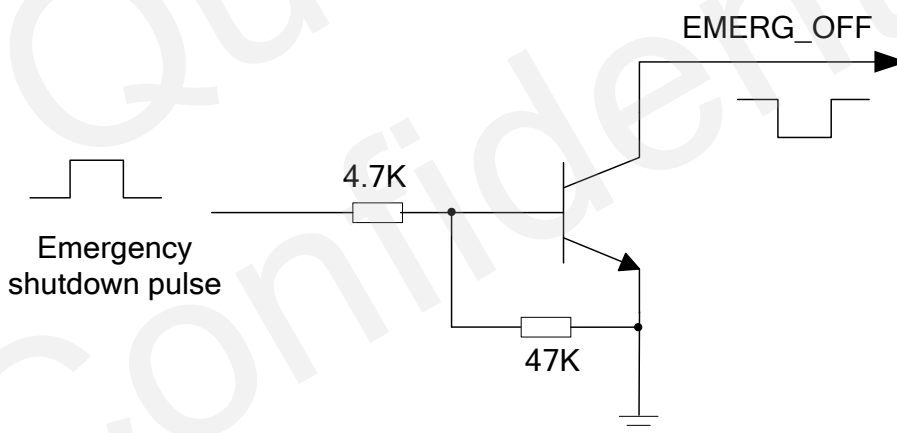


Figure 10: Reference Circuit for Driving EMERG\_OFF

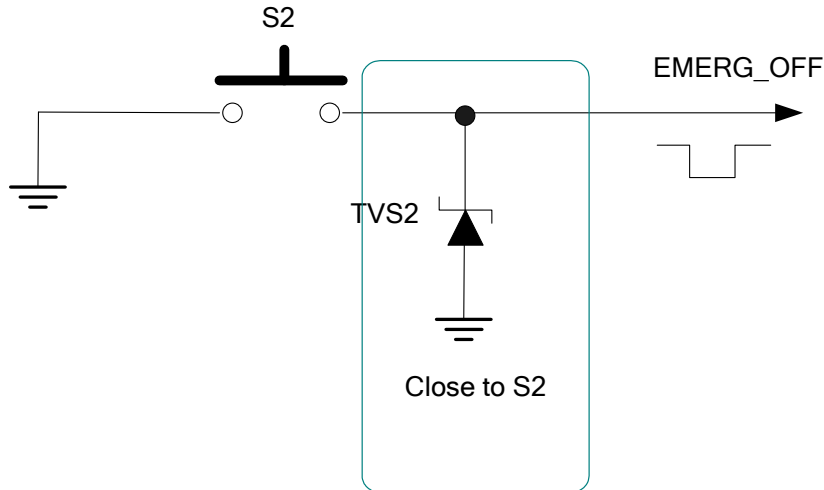


Figure 11: Reference Circuit for EMERG\_OFF by Using Button

Be cautious to use the pin EMERG\_OFF. It should only be used under emergent situation. For instance, if the module is unresponsive or abnormal, the pin EMERG\_OFF could be used to shut down the system. Although turning off the module by EMERG\_OFF is fully tested and nothing wrong detected, this operation is still a big risk as it could cause destroying of the code or data area of the flash memory in the module. Therefore, it is recommended that PWRKEY or AT command should always be the preferential way to turn off the system.

### 3.4.3. Restart Module Using the PWRKEY Pin

The module can be restarted by driving the PWRKEY to a low level voltage for a certain time, which is similar to the way of turning on module. In order to make the internal LDOs discharge completely after turning off the module, it is recommended to delay about 500ms before restarting the module. The restart timing is illustrated as the following figure.

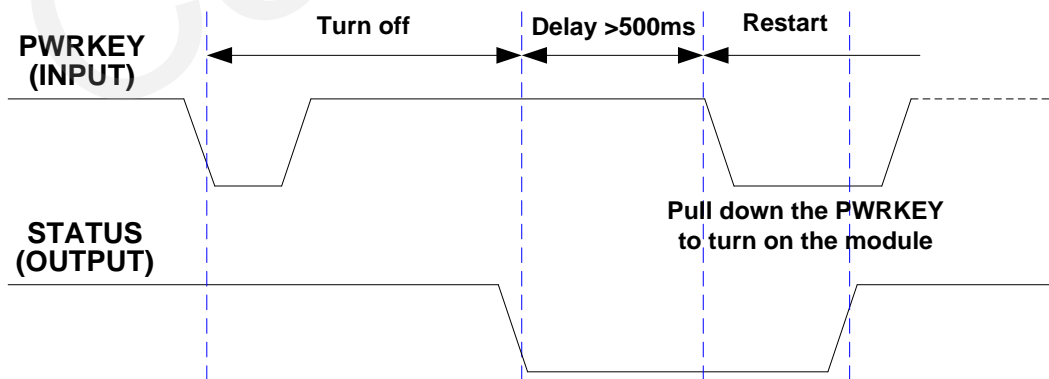


Figure 12: Timing of Restarting System

The module can also be restarted by the PWRKEY after emergency shutdown.

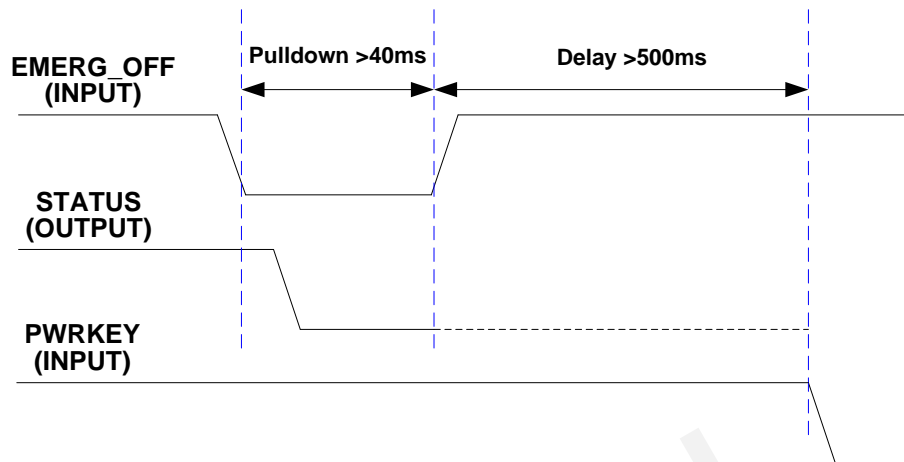


Figure 13: Timing of Restarting System after Emergency Shutdown

**NOTE**

For more details about the application of STATUS pin, please refer to the **Chapter 3.13**.

### 3.5. Power Saving

Based on system requirements, there are several actions to drive the module to enter low current consumption status. For example, “**AT+CFUN**” can be used to set module into minimum functionality mode and DTR hardware interface signal can be used to lead system to SLEEP mode.

#### 3.5.1. Minimum Functionality Mode

Minimum functionality mode reduces the functionality of the module to a minimum level. The consumption of the current can be minimized when the slow clocking mode is activated at the same time. The mode is set with the “**AT+CFUN**” command which provides the choice of the functionality levels <fun>=0, 1, 4.

- 0: minimum functionality.
- 1: full functionality (default).
- 4: disable both transmitting and receiving of RF part.

If the module is set to minimum functionality by “**AT+CFUN=0**”, the RF function and SIM card function would be disabled. In this case, the UART port is still accessible, but all AT commands related with RF function and SIM card function will be not available.

If the module has been set by the command with “**AT+CFUN=4**”, the RF function will be disabled, but the UART port is still active. In this case, all AT commands related with RF function will be not available. After the module is set by “**AT+CFUN=0**” or “**AT+CFUN=4**”, it can return to full functionality by “**AT+CFUN=1**”.

For detailed information about “**AT+CFUN**”, please refer to the *document [1]*.

### 3.5.2. SLEEP Mode (Slow Clock Mode)

The SLEEP mode is disabled by default. You can enable it by “**AT+QSCLK=1**”. On the other hand, the default setting is “**AT+QSCLK=0**” and in this mode, the module cannot enter SLEEP mode.

When the module is set by the command with “**AT+QSCLK=1**”, you can control the module to enter or exit from the SLEEP mode through pin DTR. When DTR is set to high level, and there is no on-air or hardware interrupt such as GPIO interrupt or data on UART port, the module will enter SLEEP mode automatically. In this mode, the module can still receive SMS or GPRS paging from network, but the UART port does not work.

### 3.5.3. Wake Up Module from SLEEP Mode

When the module is in the SLEEP mode, the following methods can wake up the module.

- If the DTR Pin is set low, it would wake up the module from the SLEEP mode.
- Receive a GPRS data from network will wake up module.
- Receive an SMS from network will wake up module.

#### NOTES

DTR pin should be held at low level during communication between the module and DTE.

### 3.5.4. Summary of State Transition

**Table 5: Summary of State Transition**

Current Mode	Next Mode		
	Power Down	Normal Mode	Sleep Mode
Power Down		Use PWRKEY	
Normal Mode	Use “ <b>AT+QPOWD</b> ” command, or use PWRKEY pin, or use EMERG_OFF pin		Use AT command “ <b>AT+QSCLK=1</b> ” and pull DTR up

SLEEP Mode	Use PWRKEY pin, or use EMERG_OFF pin	Pull down DTR or SMS or GPRS data transmission
------------	--------------------------------------	--

### 3.6. RTC Backup

The RTC (Real Time Clock) function is supported. The RTC is designed to work with an internal power supply.

There are three kinds of designs for RTC backup power:

- Use VBAT as the RTC power source.

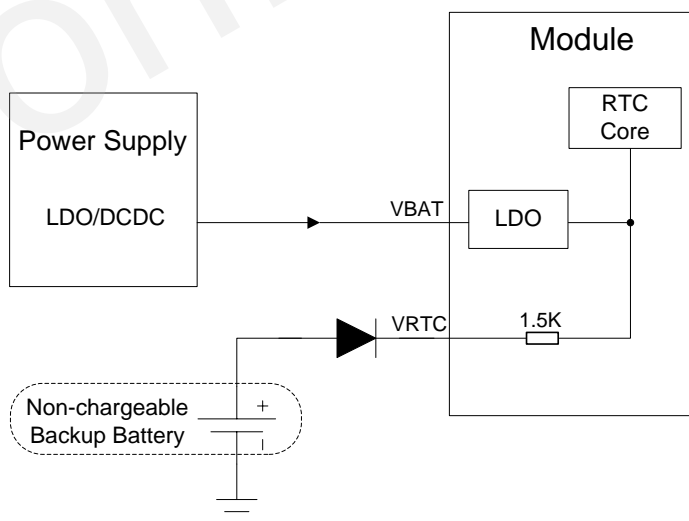
When the module is turned off and the main power supply (VBAT) is remained, the real time clock is still active as the RTC core is supplied by VBAT. In this case, the VRTC pin can be kept floating.

- Use VRTC as the RTC power source.

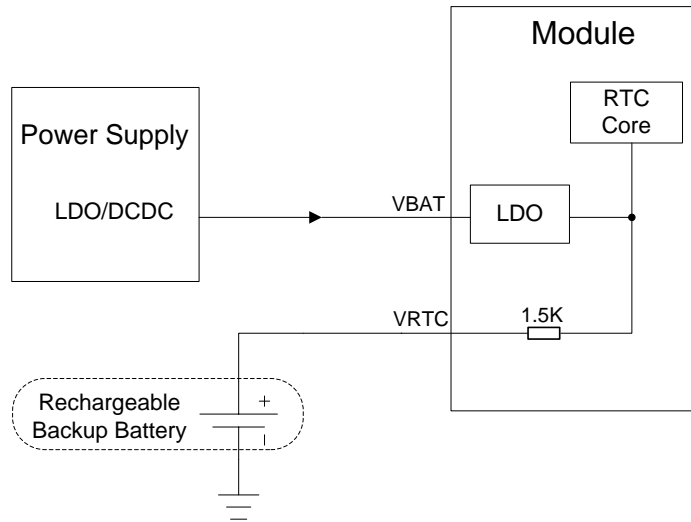
If the main power supply (VBAT) is removed after the module is turned off, a backup supply such as a coin-cell battery (rechargeable or non-chargeable) or a super-cap can be used to supply the VRTC pin to keep the real time clock active.

- Use VBAT and VRTC as the RTC power source.

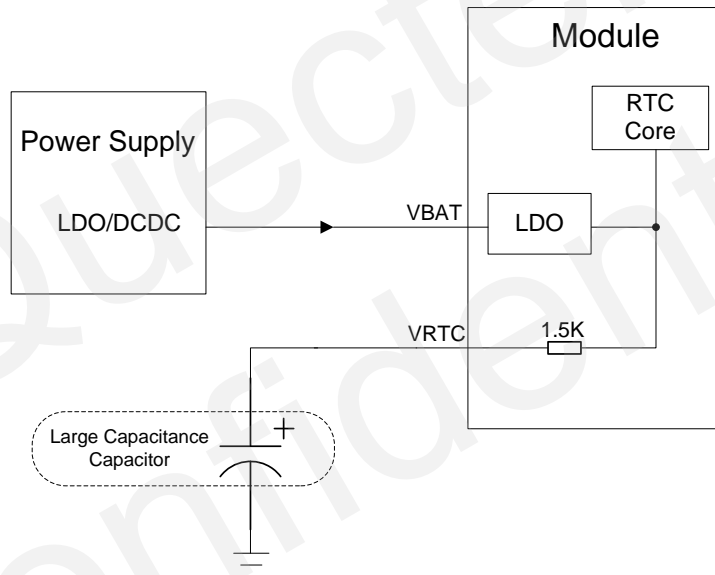
As only powering the VRTC pin to keep the RTC will lead an error about 5 minutes a day, it is recommended to power VBAT and VRTC pin at the same time when RTC function is needed. The recommended supply for RTC core circuits are shown as below.



**Figure 14: VRTC Is Supplied by a Non-chargeable Battery**



**Figure 15: VRTC Is Supplied by a Rechargeable Battery**



**Figure 16: VRTC Is Supplied by a Capacitor**

For the choice of a rechargeable or non-chargeable coin-cell battery, please visit <http://www.sii.co.jp/en/>.

**NOTE**

If you want to keep an accurate real time, please keep the main power supply VBAT alive .



### 3.7. Serial Interfaces

The module provides two serial ports: UART Port and Debug Port .The module is designed as a DCE (Data Communication Equipment), following the traditional DCE-DTE (Data Terminal Equipment) connection. Autobauding function supports baud rate from 4800bps to 115200bps.

The UART Port:

- TXD: Send data to RXD of DTE.
- RXD: Receive data from TXD of DTE.
- RTS: Request to send.
- CTS: Clear to send.
- DTR: DTE is ready and inform DCE (this pin can wake up the module).
- RI: Ring indicator (when there is a SMS or URC output, the module will inform DTE with the RI pin).
- DCD: Data carrier detection (the validity of this pin demonstrates the communication link is set up).

#### NOTE

Hardware flow control is disabled by default. When hardware flow control is required, RTS and CTS should be connected to the host. AT command “**AT+IFC=2,2**” is used to enable hardware flow control. AT command “**AT+IFC=0,0**” is used to disable the hardware flow control. For more details, please refer to the [document \[1\]](#).

The Debug Port:

- DBG\_TXD: Send data to the COM port of computer.
- DBG\_RXD: Receive data from the COM port of computer.

The logic levels are described in the following table.

**Table 6: Logic Levels of the UART Interfaces**

Parameter	Min.	Max.	Unit
VIL	0	0.25×VDD_EXT	V
VIH	0.75×VDD_EXT	VDD_EXT +0.2	V
VOL	0	0.15×VDD_EXT	V
VOH	0.85×VDD_EXT	VDD_EXT	V

**Table 7: Pin Definition of the UART Interfaces**

Interfaces	Pin No.	Pin Name	Description
Debug Port	18	DBG_RXD	Receive data of the debug port
	19	DBG_TXD	Transmit data of the debug port
UART Port	5	DTR	Data terminal ready
	2	RXD	Receive data
	1	TXD	Transmit data
	4	CTS	Clear to send
	3	RTS	Request to send
	20	DCD	Data carrier detection
	23	RI	Ring indication

### 3.7.1. UART Port

#### 3.7.1.1. The Features of UART Port

- Seven lines on UART interface.
- Contain data lines TXD and RXD, hardware flow control lines RTS and CTS, other control lines DTR, DCD and RI.
- Used for AT command, GPRS data, etc. Multiplexing function is supported on the UART Port. So far only the basic mode of multiplexing is available.
- Support the communication baud rates as the following:  
300, 600, 1200, 2400, 4800, 9600, 14400, 19200, 28800, 38400, 57600 and 115200.
- The default setting is autobauding mode. Support the following baud rates for autobauding function:  
4800, 9600, 19200, 38400, 57600, 115200.
- The module disables hardware flow control by default. AT command “**AT+IFC=2,2**” is used to enable hardware flow control.

After setting a fixed baud rate or autobauding, please send “AT” string at that rate. The UART port is ready when it responds “OK”.

Autobauding allows the module to detect the baud rate by receiving the string “AT” from the host or PC automatically, which gives module flexibility without considering which baud rate is used by the host controller. Autobauding is enabled by default. To take advantage of the autobauding mode, special attention should be paid according to the following requirements:

## 1. Synchronization between DTE and DCE:

When DCE (the module) powers on with the autobauding enabled, it is recommended to wait 4 or 5 seconds before sending the first AT character. After receiving the “OK” response, DTE and DCE are correctly synchronized.

If the host controller needs URC in the mode of autobauding, it must be synchronized firstly. Otherwise the URC will be discarded.

## 2. Restrictions on autobauding operation:

- The UART port has to be operated at 8 data bits, no parity and 1 stop bit (factory setting).
- Only the strings “AT” or “at” can be detected (neither “At” nor “aT”).
- The Unsolicited Result Codes like “RDY”, “+CFUN: 1” and “+CPIN: READY” will not be indicated when the module is turned on with autobauding enabled and not be synchronized.
- Any other Unsolicited Result Codes will be sent at the previous baud rate before the module detects the new baud rate by receiving the first “AT” string. The DTE may receive unknown characters after switching to new baud rate.
- It is not recommended to switch to autobauding from a fixed baud rate.
- If autobauding is active, it is not recommended to switch to multiplex mode.

### NOTE

To assure reliable communication and avoid any problems caused by undetermined baud rate between DCE and DTE, it is strongly recommended to configure a fixed baud rate and save it instead of using autobauding after start-up. For more details, please refer to the Section “AT+IPR” in *document [1]*.

### 3.7.1.2. Reference Design for UART Port

The connection between module and host using UART Port is very flexible. Three connection styles are illustrated as below.

Reference design for Full-Function UART connection is shown as below when it is applied in modulation-demodulation.

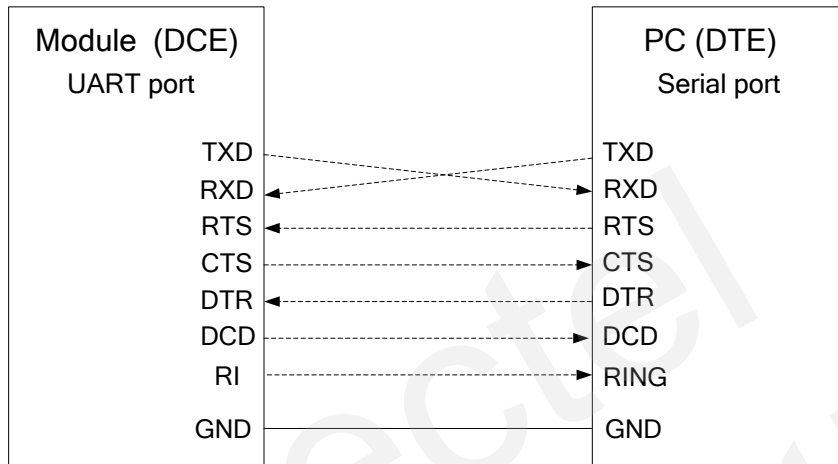


Figure 17: Reference Design for Full-Function UART

Three-line connection is shown as below.

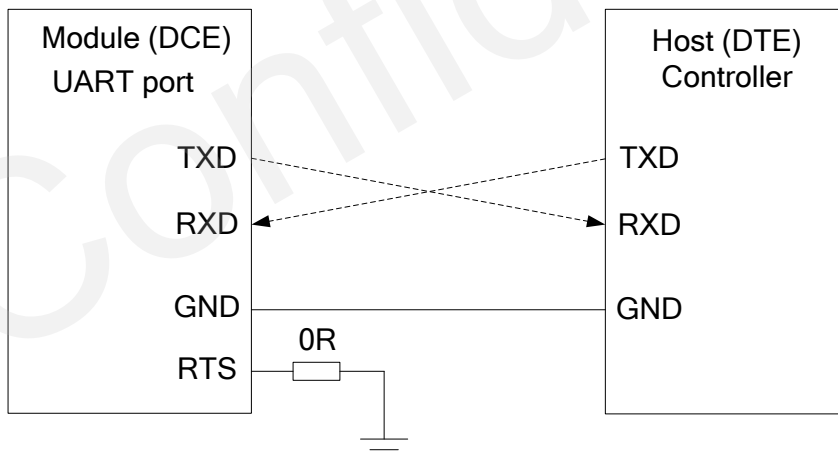
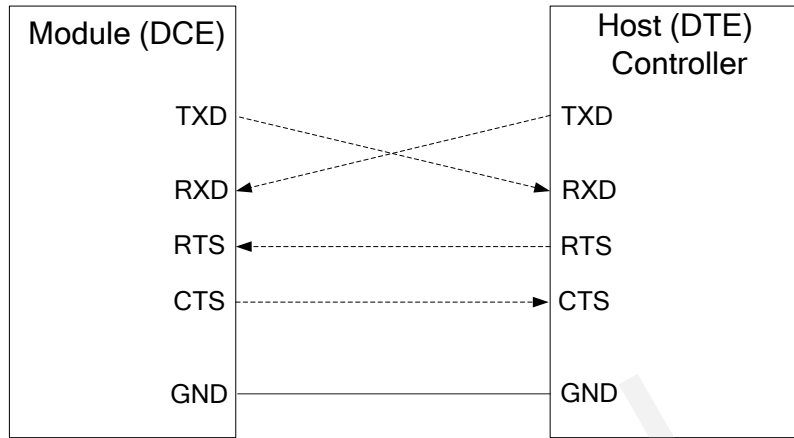


Figure 18: Reference Design for three-line UART Port

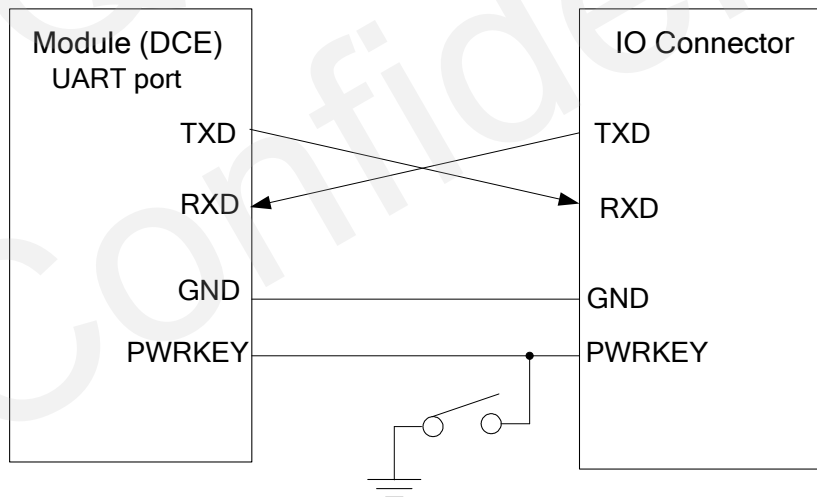
The reference design with hardware flow control is shown as below. This connection will enhance the reliability of the mass data communication.



**Figure 19: Reference Design with Hardware Flow Control**

### 3.7.1.3. Firmware Upgrade

The TXD, RXD can be used to upgrade firmware. The PWRKEY pin must be pulled down before firmware upgrade. The reference circuit is shown as below:



**Figure 20: Reference Design for Firmware Upgrade**

**NOTE**

The firmware of module might need to be upgraded due to certain reasons. It is recommended to reserve these pins in the host board for firmware upgrade.

### 3.7.2. Debug Port

Debug Port:

- Two lines: DBG\_TXD and DBG\_RXD
- It outputs log information automatically.
- Debug Port is only used for firmware debugging and its baud rate must be configured as 460800bps.

The following figure is the reference design for software debug.

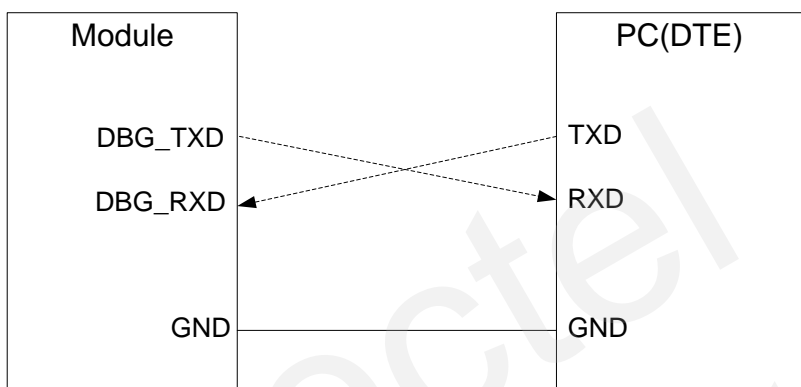


Figure 21: Reference Design for Debug Port

### 3.7.3. UART Application

The reference design of 3.3V level match is shown as below. When the peripheral MCU/ARM system is 3V, the divider resistor should be changed from 5.6K to 10K.

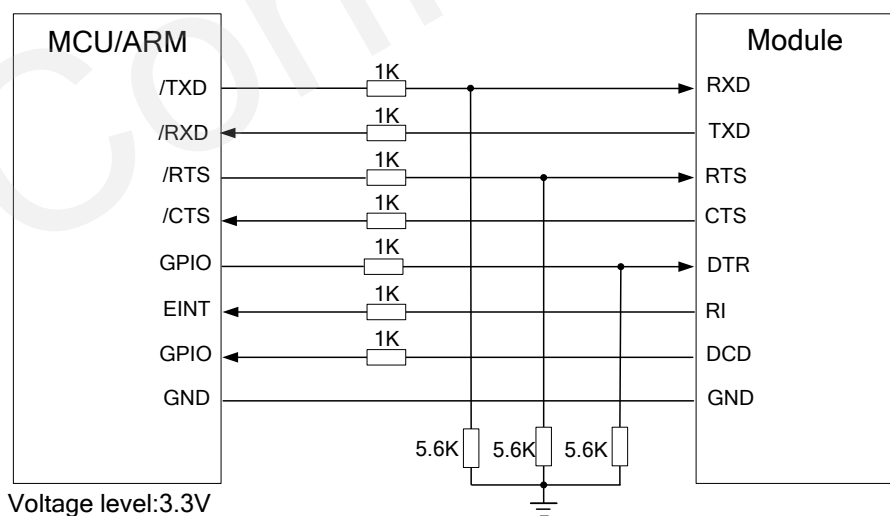
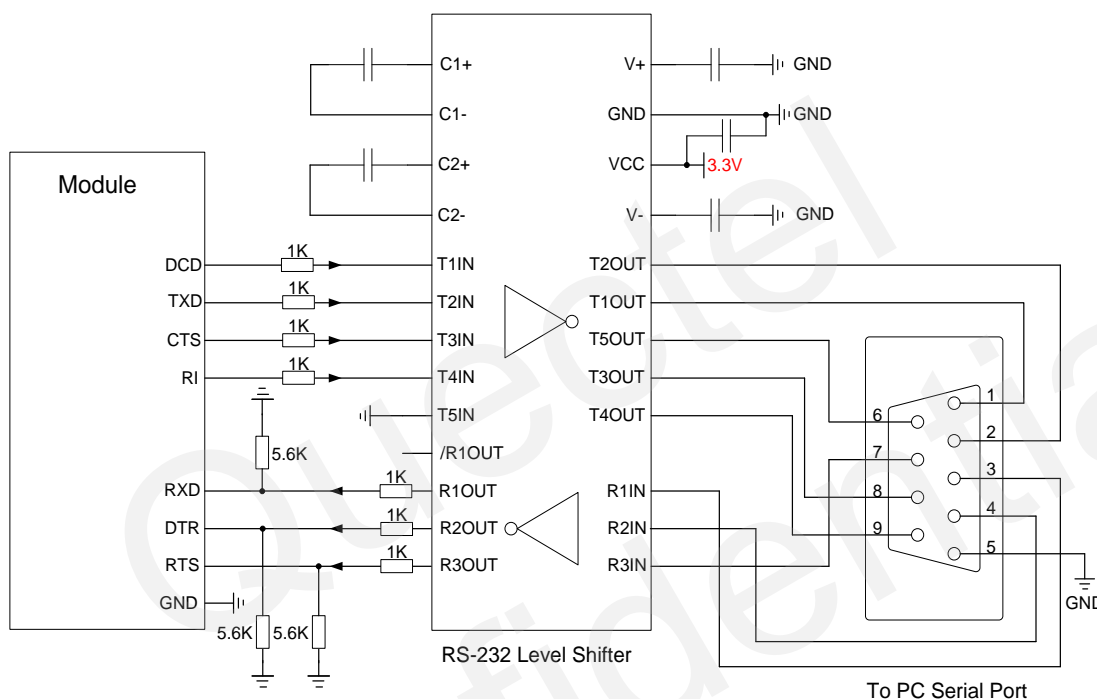


Figure 22: Level Match Design for 3.3V System

**NOTE**

It is highly recommended to add the resistor divider circuit on the UART signal lines when the host's level is 3V or 3.3V. For the higher voltage level system, a level shifter IC could be used between the host and the module. For more details about UART circuit design, please refer to **document [5]**.

The following figure shows a sketch map between module and standard RS-232 interface. Since the electrical level of module is 2.8V, so a RS-232 level shifter must be used. Note that you should assure the IO voltage of level shifter which connects to module is 2.8V.



**Figure 23: Sketch Map for RS-232 Interface Match**

Please visit vendor website to select the suitable RS-232 level shifter IC, such as: <http://www.maximintegrated.com> and <http://www.exar.com/>.

### 3.8. SIM Card Interface

The SIM interface supports the functionality of the GSM Phase 1 specification and also supports the functionality of the new GSM Phase 2+ specification for FAST 64 kbps SIM card, which is intended to use with a SIM application Tool-kit.

The SIM interface is powered by an internal regulator in the module. Both 1.8V and 3.0V SIM cards are supported.

**Table 8: Pin Definition of the SIM Interface**

Pin NO.	Name	Description
11	SIM_VDD	Supply power for SIM card. Automatic detection of SIM card voltage. 3.0V±5% and 1.8V±5%. Maximum supply current is around 10mA.
12	SIM_CLK	SIM card clock.
10	SIM_DATA	SIM card data I/O.
13	SIM_RST	SIM card reset.
9	SIM_PRESENCE	SIM card presence detection
8	SIM_GND	SIM card ground.

The following figure is the reference design for SIM interface, and here an 8-pin SIM card holder is used.

The pin SIM\_PRESENCE is used to detect whether the tray of the Molex SIM socket, which is used for holding SIM card, is present in the card socket. When the tray is inserted into the socket, SIM\_PRESENCE is at low level. Regardless of whether the SIM card is in the tray or not, the change of SIM\_PRESENCE level from high to low level inspires the module to reinitialize SIM card. In default configuration, SIM card detection function is disabled. Customer's application can use "AT+QSIMDET=1, 0" to switch on and "AT+QSIMDET=0, 0" to switch off the SIM card detection function. For details of this AT command, please refer to *document [1]*. When "AT+QSIMDET=1, 0" is set and the tray with SIM card is removed from SIM socket, the following URC will be presented.

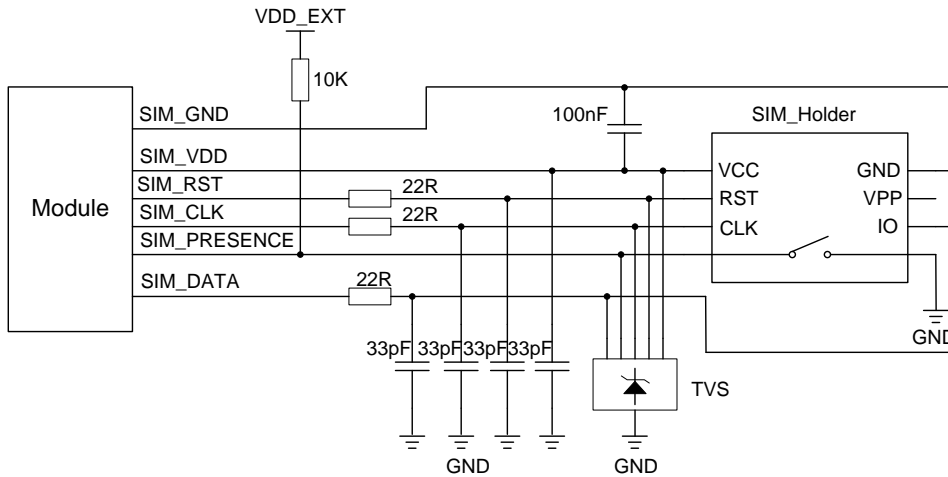
**+CPIN: NOT INSERTED**

When the tray with SIM card is inserted into SIM card socket again and the module finishes re-initialization SIM card, the following URC will be presented.

**+CPIN: READY**

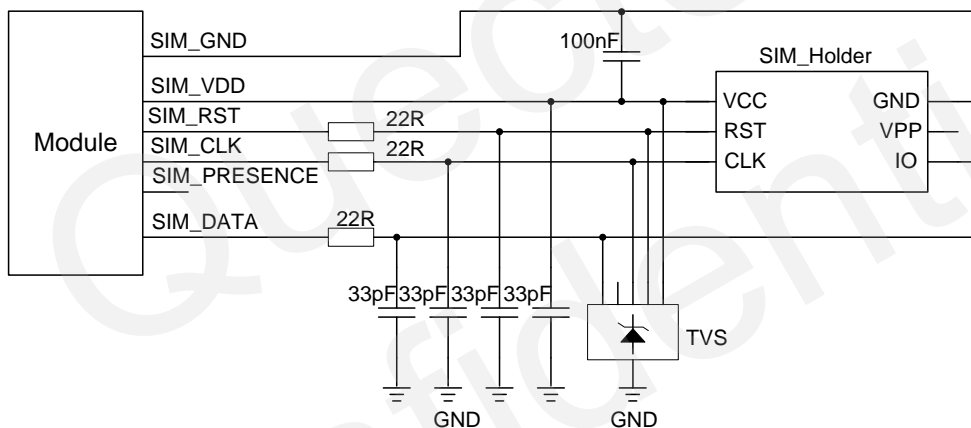
*Call Ready*





**Figure 24: Reference Circuit for 8-pin SIM Card Holder**

If SIM card detection function is not used, keep SIM\_PRESENCE pin open. The reference circuit for a 6-pin SIM card socket is illustrated as the following figure.



**Figure 25: Reference Circuit for 6-pin SIM Card Holder**

For more information of SIM card holder, please visit <http://www.amphenol.com> and <http://www.molex.com>.

In order to enhance the reliability and availability of the SIM card in application. Please follow the below criterion in the SIM circuit design.

- Keep layout of SIM card as close as possible to the module. Assure the possibility of the length of the trace is less than 200mm.
- Keep SIM card signals away from RF and VBAT alignment.
- Assure the ground between module and SIM cassette short and wide. Keep the width of ground no less than 0.5mm to maintain the same electric potential. The decouple capacitor of SIM\_VDD is less than 1uF and must be near to SIM cassette.
- To avoid cross talk between SIM\_DATA and SIM\_CLK. Keep them away with each other and shield

them with surrounded ground. For good performance, the SIM\_RST line also should be protected by the ground.

- In order to offer good ESD protection, it is recommended to add a TVS diode array. For more information of TVS diode, please visit <http://www.onsemi.com/>. The most important rule is to place the ESD protection device close to the SIM card socket and make sure the nets being protected will go through the ESD device first and then lead to module. The 22Ω resistors should be connected in series between the module and the SIM card so as to suppress the EMI spurious transmission and enhance the ESD protection. Please to be noted that the SIM peripheral circuit should be close to the SIM card socket.
- Place the RF bypass capacitors (33pF) close to the SIM card on all signal lines to filter away the possible RF noise.

### 3.9. Behaviors of The RI

Table 9: Behaviors of the RI

State	RI Response
Standby	HIGH
SMS	When a new SMS comes, the RI changes to LOW and holds low level for about 120 ms, then changes to HIGH.
URC	Certain URCs can trigger 120ms low level on RI.

**NOTE**

If URC of SMS is disabled, the RI will not change.

The timing of the RI is shown as below.

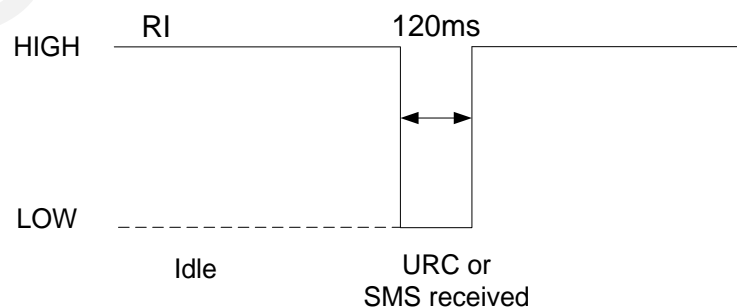


Figure 26: RI Behaviours of URC or SMS Received

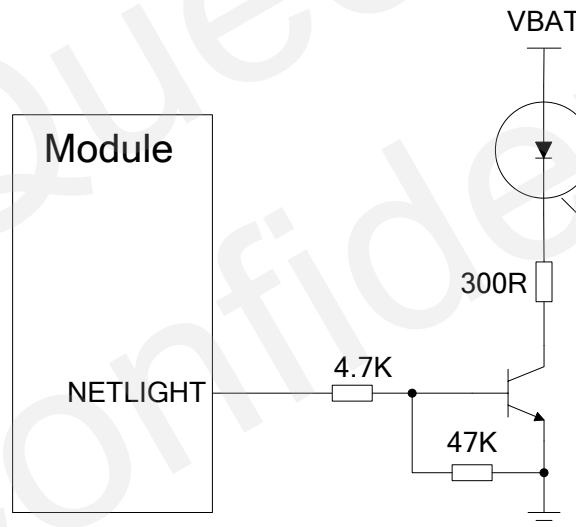
### 3.10. Network Status Indication

The NETLIGHT signal can be used to drive a network status indicator LED. The working state of this pin is listed in Table 10, and a reference circuit is shown as below.

**Table 10: Working State of the NETLIGHT**

State	Module Function
Off	The module is not running.
64ms On/800ms Off	The module is not synchronized with network.
64ms On/2000ms Off	The module is synchronized with network.
64ms On/600ms Off	The GPRS data transmission after dialing the PPP connection.

A reference circuit is shown as below.



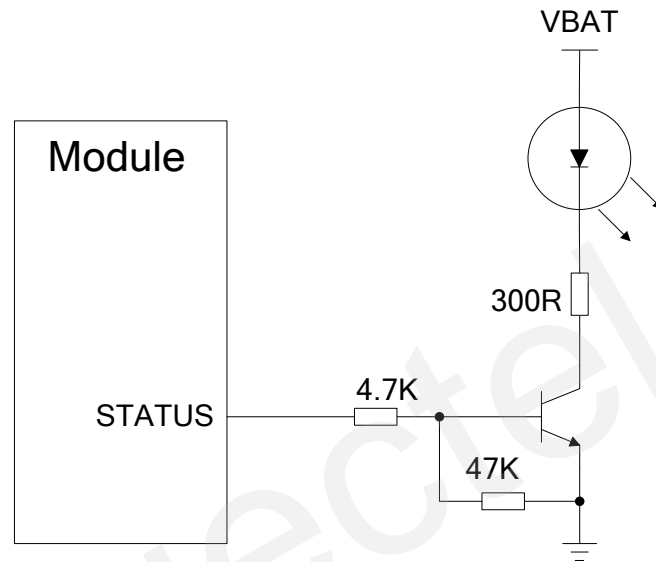
**Figure 27: Reference Design for NETLIGHT**

### 3.11. Operating Status Indication

The STATUS pin will output a high level after the module being turned on, but it is not recommended connecting this pin to a MCU's GPIO to judge whether the module is turn-on or not. The following LED indicator circuit for STATUS pin can be used to indicate the state after the module has been turned on.

**Table 11: Pin Definition of the STATUS**

Name	Pin	Description
STATUS	22	Indicate module operating status



**Figure 28: Reference Design for STATUS**

# 4 Antenna Interface

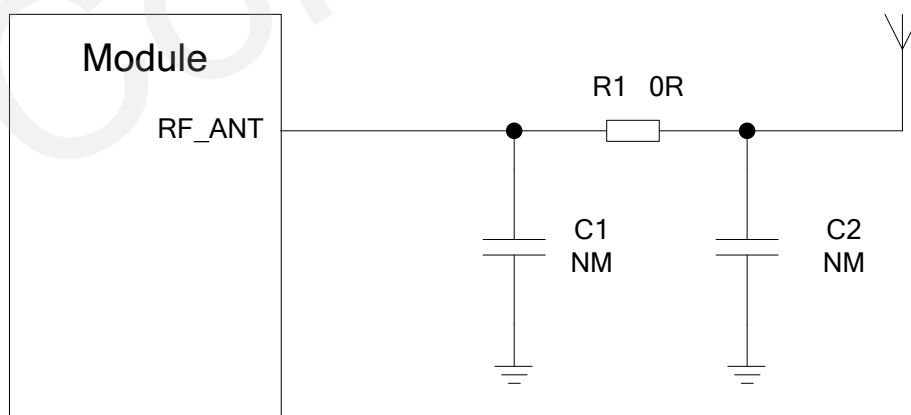
The Pin 28 is the RF antenna pad. The RF interface has an impedance of 50Ω.

**Table 12: Pin Definition of the RF\_ANT**

Name	Pin	Description
GND	26	Ground
GND	27	Ground
RF_ANT	28	RF antenna pad
GND	29	Ground
GND	30	Ground

## 4.1. RF Reference Design

A reference circuit is shown in following figure. In order to adjust RF performance, it should reserve a  $\Pi$ -type matching circuit. By default, the resistance of R1 is 0Ω and capacitors C1 and C2 are not soldered.



**Figure 29: Reference Design for RF**

M72 provides an RF antenna pad for antenna connection. The RF trace in host PCB connected to the module RF antenna pad should be coplanar waveguide line or micro-strip line, whose characteristic resistance should be close to 50Ω. M72 comes with two grounding pads which are next to the antenna pad in order to give a better grounding.

## 4.2. RF Output Power

**Table 13: The Module Conducted RF Output Power**

Frequency	Max.	Min.
EGSM900	33dBm±2dB	5dBm±5dB
DCS1800	30dBm±2dB	0dBm±5dB

### NOTE

In GPRS 4 slots TX mode, the max output power is reduced by 2.5dB. This design conforms to the GSM specification as described in section 13.16 of **3GPP TS 51.010-1**.

## 4.3. RF Receiving Sensitivity

**Table 14: The Module Conducted RF Receiving Sensitivity**

Frequency	Receive Sensitivity
EGSM900	< -109dBm
DCS1800	< -109dBm

## 4.4. Operating Frequencies

**Table 15: The Module Operating Frequencies**

Frequency	Receive	Transmit	ARFCH
EGSM900	925~960MHz	880~915MHz	0~124, 975~1023
DCS1800	1805~1880MHz	1710~1785MHz	512~885

## 4.5. Antenna Requirement

The following table shows the requirement on GSM antenna.

**Table 16: Antenna Cable Requirements**

Type	Requirements
EGSM900	Cable insertion loss <1dB
DCS1800	Cable insertion loss <1.5dB

**Table 17: Antenna Requirements**

Type	Requirements
Frequency Range	EGSM900/DCS1800
VSWR	≤ 2
Gain (dBi)	1
Max Input Power (W)	50
Input Impedance (Ω)	50
Polarization Type	Vertical

## 4.6. Recommendation of RF Pad Welding

Soldering the RF cable to RF pad of module correctly will reduce the loss on the path of RF, please refer to the following example of RF soldering.

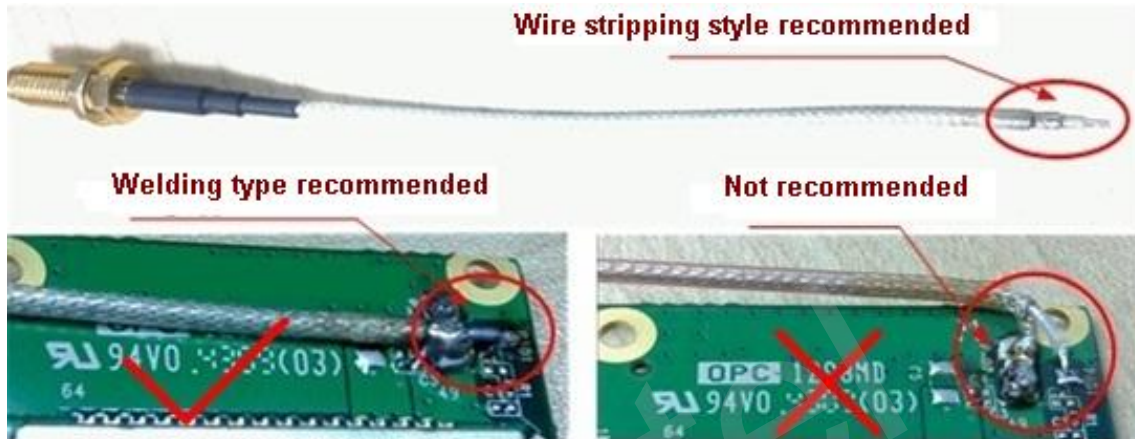


Figure 30: RF Soldering Sample



# 5 Electrical, Reliability and Radio Characteristics

## 5.1. Absolute Maximum Ratings

Absolute maximum ratings for power supply and voltage on digital and analog pins of module are listed in the following table:

**Table 18: Absolute Maximum Ratings**

Parameter	Min.	Max.	Unit
VBAT	-0.3	+4.73	V
Peak Current of Power Supply	0	2	A
RMS Current of Power Supply (during one TDMA- frame)	0	0.7	A
Voltage at Digital Pins	-0.3	3.08	V
Voltage at Analog Pins	-0.3	3.08	V
Voltage at Digital/Analog Pins in Power Down Mode	-0.25	0.25	V

## 5.2. Operating Temperature

The operating temperature is listed in the following table:

**Table 19: Operating Temperature**

Parameter	Min.	Typ.	Max.	Unit
Normal Temperature	-35	+25	+80	°C

Restricted Operation <sup>1)</sup>	-40 ~ -35	+80 ~ +85	°C
Storage Temperature	-45	+90	°C

**NOTE**

<sup>1)</sup> When the module works within this temperature range, the deviation from the GSM specification may occur. For example, the frequency error or the phase error will be increased.

### 5.3. Power Supply Ratings

**Table 20: The Module Power Supply Ratings**

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit	
VBAT	Supply voltage	Voltage must stay within the min/max values, including voltage drop, ripple, and spikes.	3.3	4.0	4.6	V	
	Voltage drop during transmitting burst	Maximum power control level on EGSM900.			400	mV	
IVBAT	Average supply current	Power down mode		150		uA	
		SLEEP mode @DRX=5		1.3		mA	
		Minimum functionality mode AT+CFUN=0					
		IDLE mode			13		mA
		SLEEP mode			0.98		mA
		AT+CFUN=4					
		IDLE mode			13		mA
		SLEEP mode			1.0		mA
		DATA mode, GPRS (3Rx, 2Tx) EGSM900 <sup>1)</sup>			393		mA
		DCS1800 <sup>2)</sup>			268		mA
DATA mode, GPRS(2Rx,3Tx) EGSM900 <sup>1)</sup>			546		mA		
DCS1800 <sup>2)</sup>			366		mA		
DATA mode, GPRS (4Rx,1Tx) EGSM900 <sup>1)</sup>			234		mA		
DCS1800 <sup>2)</sup>			172		mA		
DATA mode, GPRS (1Rx,4Tx) EGSM900 <sup>1)</sup>			485 <sup>3)</sup>		mA		

	DCS1800 <sup>2)</sup>	462	mA
Peak supply current (during transmission slot)	Maximum power control level on EGSM900.	1.6	2 A

### NOTES

- 1) Power control level PCL 5.
- 2) Power control level PCL 0.
- 3) Under the EGSM900 spectrum, the power of 1Rx and 4Tx has been reduced.

## 5.4. Current Consumption

The values of current consumption are shown as below.

**Table 21: The Module Current Consumption**

Condition	Current Consumption
<b>GPRS Data</b>	
DATA mode, GPRS (3Rx, 2Tx) CLASS 12	
EGSM900	@power level #5 <550mA, Typical 393mA
	@power level #12, Typical 132mA
	@power level #19, Typical 92mA
DCS1800	@power level #0 <450mA, Typical 268mA
	@power level #7, Typical 112mA
	@power level #15, Typical 88mA
DATA mode, GPRS (2Rx, 3Tx) CLASS 12	
EGSM900	@power level #5 <600mA, Typical 546mA
	@power level #12, Typical 160mA
	@power level #19, Typical 101mA
DCS1800	@power level #0 <490mA, Typical 366mA
	@power level #7, Typical 131mA
	@power level #15, Typical 93mA
DATA mode, GPRS (4Rx,1Tx) CLASS 12	
EGSM900	@power level #5 <350mA, Typical 233mA
	@power level #12, Typical 104mA

	@power level #19, Typical 84mA
DCS1800	@power level #0 <300mA, Typical 171mA @power level #7, Typical 96mA @power level #15, Typical 82mA
DATA mode, GPRS (1Rx, 4Tx) CLASS 12	
EGSM900	@power level #5 <660mA, Typical 484mA @power level #12, Typical 187mA @power level #19, Typical 109mA
DCS1800	@power level #0 <530mA, Typical 461mA @power level #7, Typical 149mA @power level #15, Typical 97mA

**NOTE**

GPRS Class 12 is the default setting. The module can be configured from GPRS Class1 to Class12. Setting to lower GPRS class would make it easier to design the power supply for the module.

### 5.5. Electro-static Discharge

Although the GSM engine is generally protected against Electro-static Discharge (ESD), ESD protection precautions should still be emphasized. Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any applications using the module.

The measured ESD values of module are shown as the following table:

**Table 22: The ESD Endurance (Temperature: 25°C, Humidity: 45 %)**

Tested Point	Contact Discharge	Air Discharge
VBAT, GND	±5KV	±10KV
RF_ANT	±5KV	±10KV
TXD, RXD	±2KV	±4KV
Others	±0.5KV	±1KV

# 6 Mechanical Dimensions

This chapter describes the mechanical dimensions of the module.

## 6.1. Mechanical Dimensions of Module

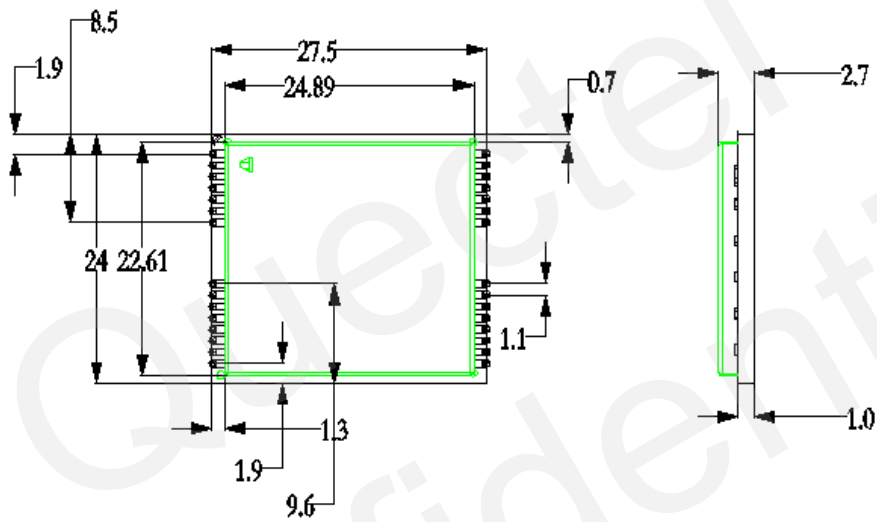


Figure 31: M72 Top and Side Dimensions (Unit: mm)

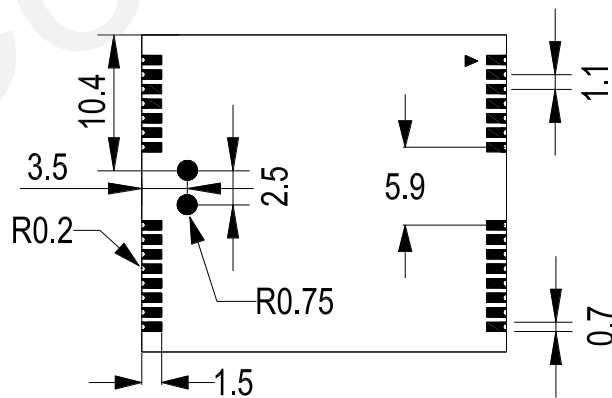


Figure 32: M72 Bottom Dimensions (Unit: mm)

## 6.2. Recommended Footprint

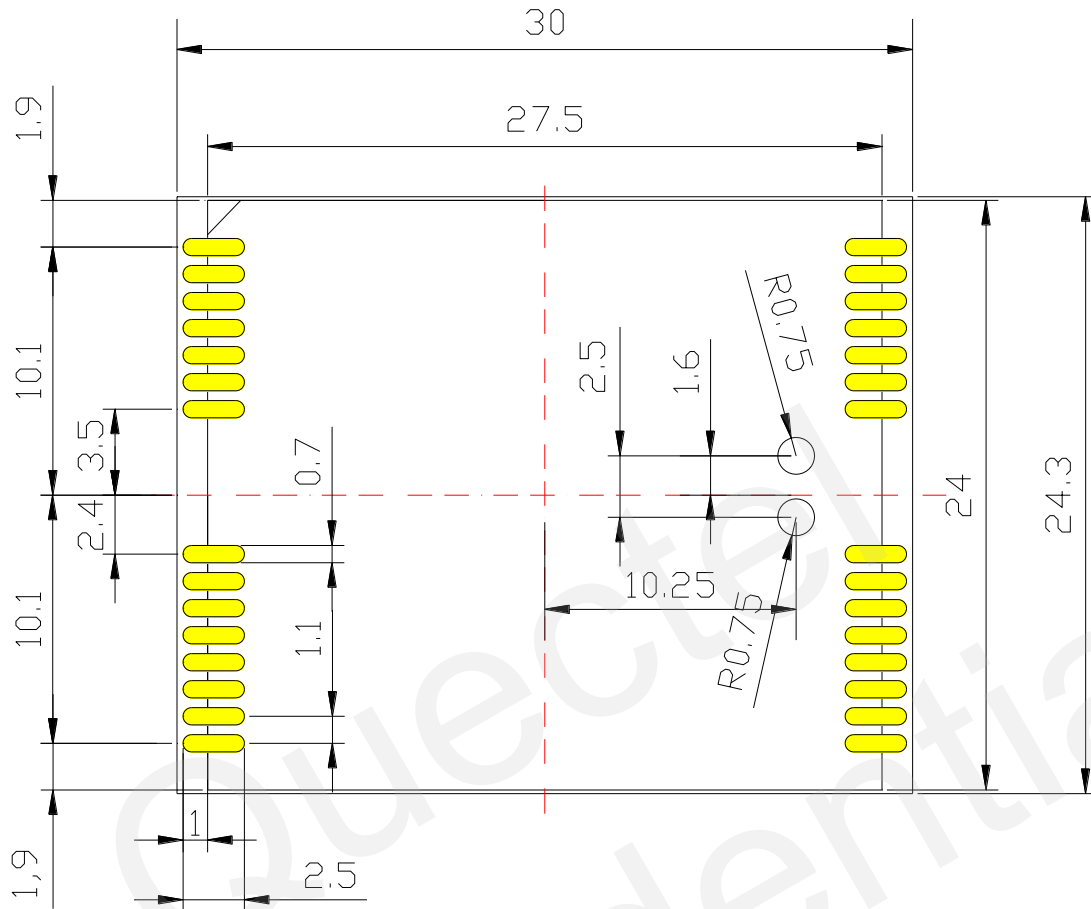


Figure 33: Recommended Footprint (Unit: mm)

### NOTES

1. The module should be kept about 3mm away from other components in the host PCB.
2. The circular test points with a radius of 0.75mm in the above recommended footprint should be treated as keepout areas (“keepout” means do not pour copper on the mother board).

### 6.3. Top View of the Module

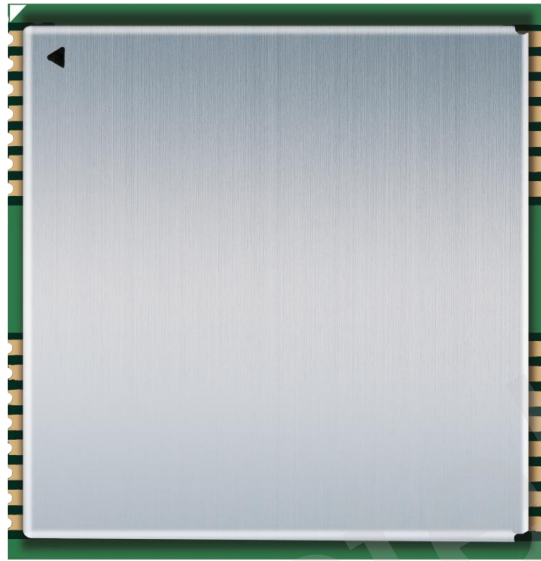


Figure 34: Top View of the Module

### 6.4. Bottom View of the Module

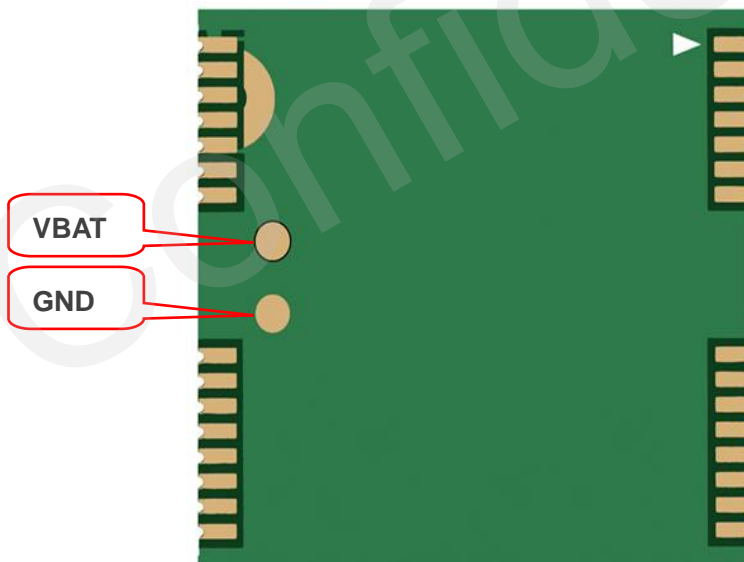


Figure 35: Bottom View of the Module

# 7 Storage and Manufacturing

## 7.1. Storage

M72 module is distributed in a vacuum-sealed bag. The restriction for storage is shown as below.

Shelf life in the vacuum-sealed bag: 12 months at environments of  $<40^{\circ}\text{C}$  temperature and  $<90\% \text{RH}$ .

After the vacuum-sealed bag is opened, devices that need to be mounted directly must be:

- Mounted within 72 hours at the factory environment of  $\leq 30^{\circ}\text{C}$  temperature and  $<60\% \text{RH}$ .
- Stored at  $<10\% \text{RH}$ .

Devices require baking before mounting, if any circumstance below occurs.

- When the ambient temperature is  $23^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , humidity indication card shows the humidity is  $>10\%$  before opening the vacuum-sealed bag.
- If ambient temperature is  $<30^{\circ}\text{C}$  and the humidity is  $<60\%$ , the devices have not been mounted during 72hours.
- Stored at  $>10\% \text{RH}$ .

If baking is required, devices should be baked for 48 hours at  $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$ .

### NOTE

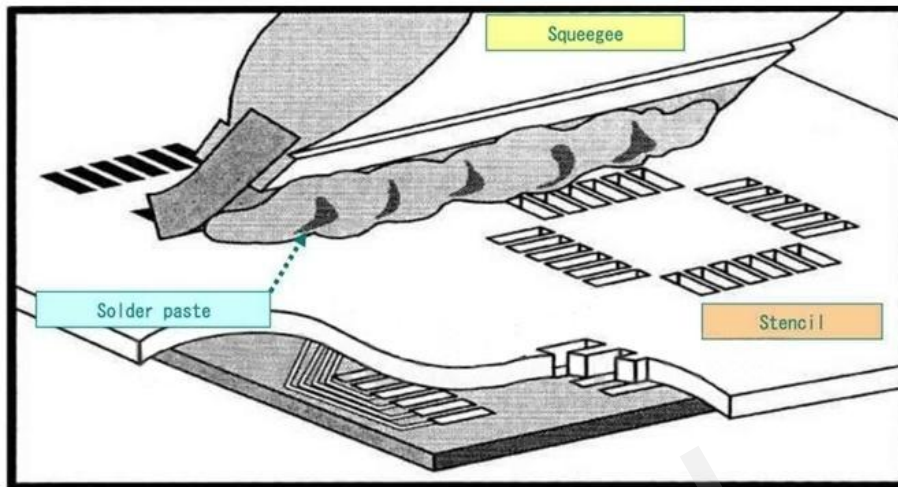
As plastic container cannot be subjected to high temperature, devices must be removed prior to high temperature ( $125^{\circ}\text{C}$ ) bake. If shorter bake times are desired, refer to the IPC/JEDECJ-STD-033 for bake procedure.

## 7.2. Soldering

The squeegee should push the paste on the surface of the stencil that makes the paste fill the stencil openings and penetrate to the PCB. The force on the squeegee should be adjusted so as to produce a clean stencil surface on a single pass. To ensure the module soldering quality, the thickness of stencil at

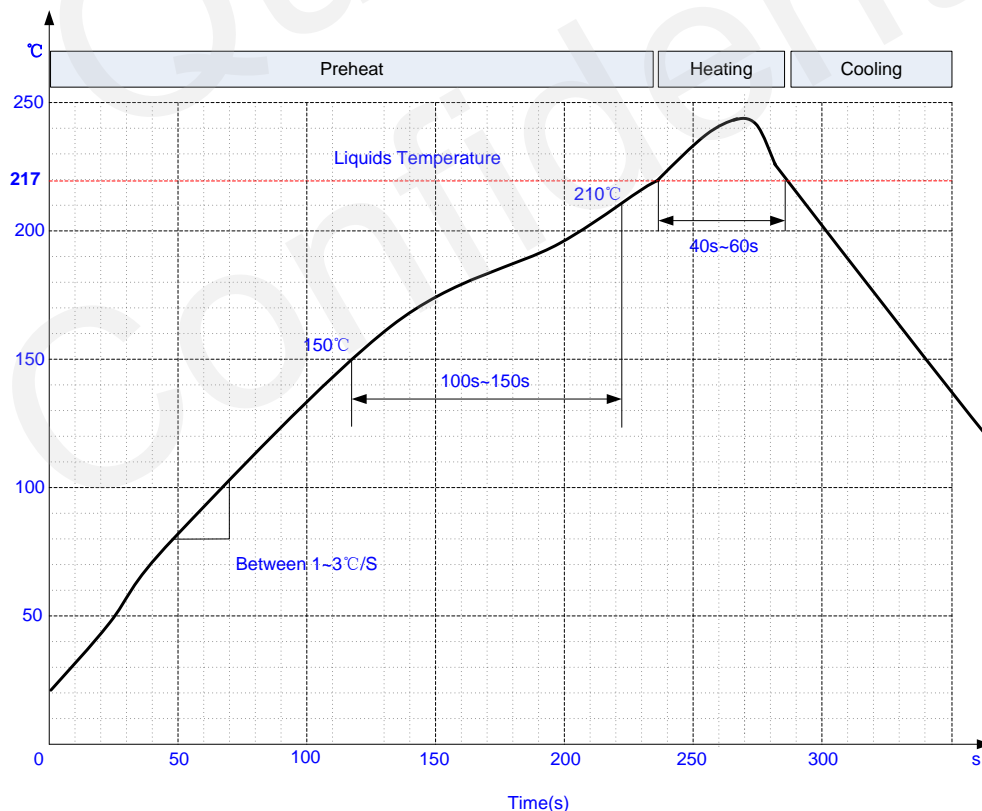


the hole of the module pads should be 0.2 mm for M72. For more details, please refer to *document [3]*.



**Figure 36: Paste Application**

It is suggested that peak reflow temperature is from 235 °C to 245°C (for SnAg3.0Cu0.5 alloy). Absolute max reflow temperature is 260°C. To avoid damage to the module when it was repeatedly heated, it is suggested that the module should be mounted after the first panel has been reflowed. The following picture is the actual diagram which we have operated.

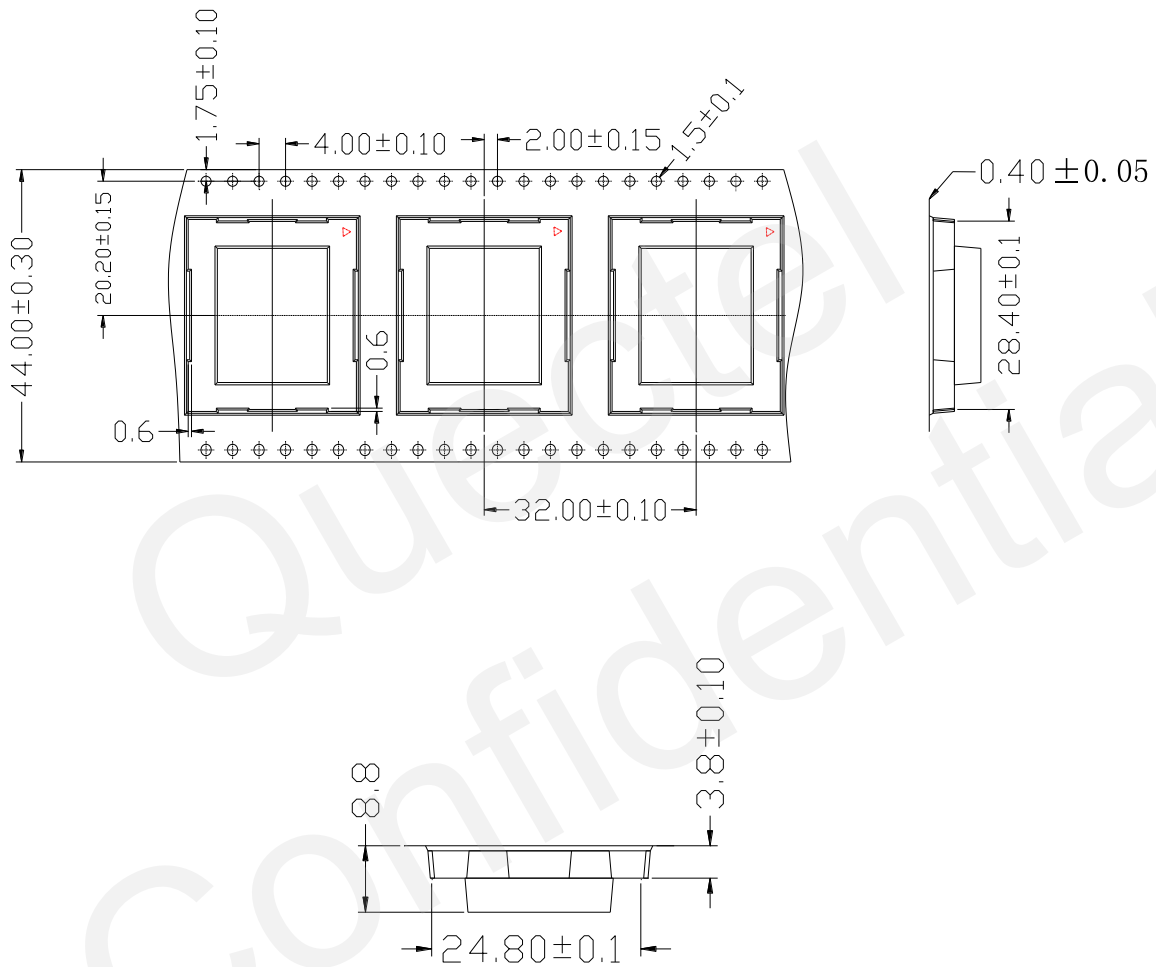


**Figure 37: Ramp-Soak-Spike Reflow Profile**

### 7.3. Packaging

The modules are stored inside a vacuum-sealed bag which is ESD protected. It should not be opened until the devices are ready to be soldered onto the application.

M72 is shipped in tape and reel form. The reel is 330mm in diameter and each reel contains 250pcs modules.



**Figure 38: Tape and Reel Specification**

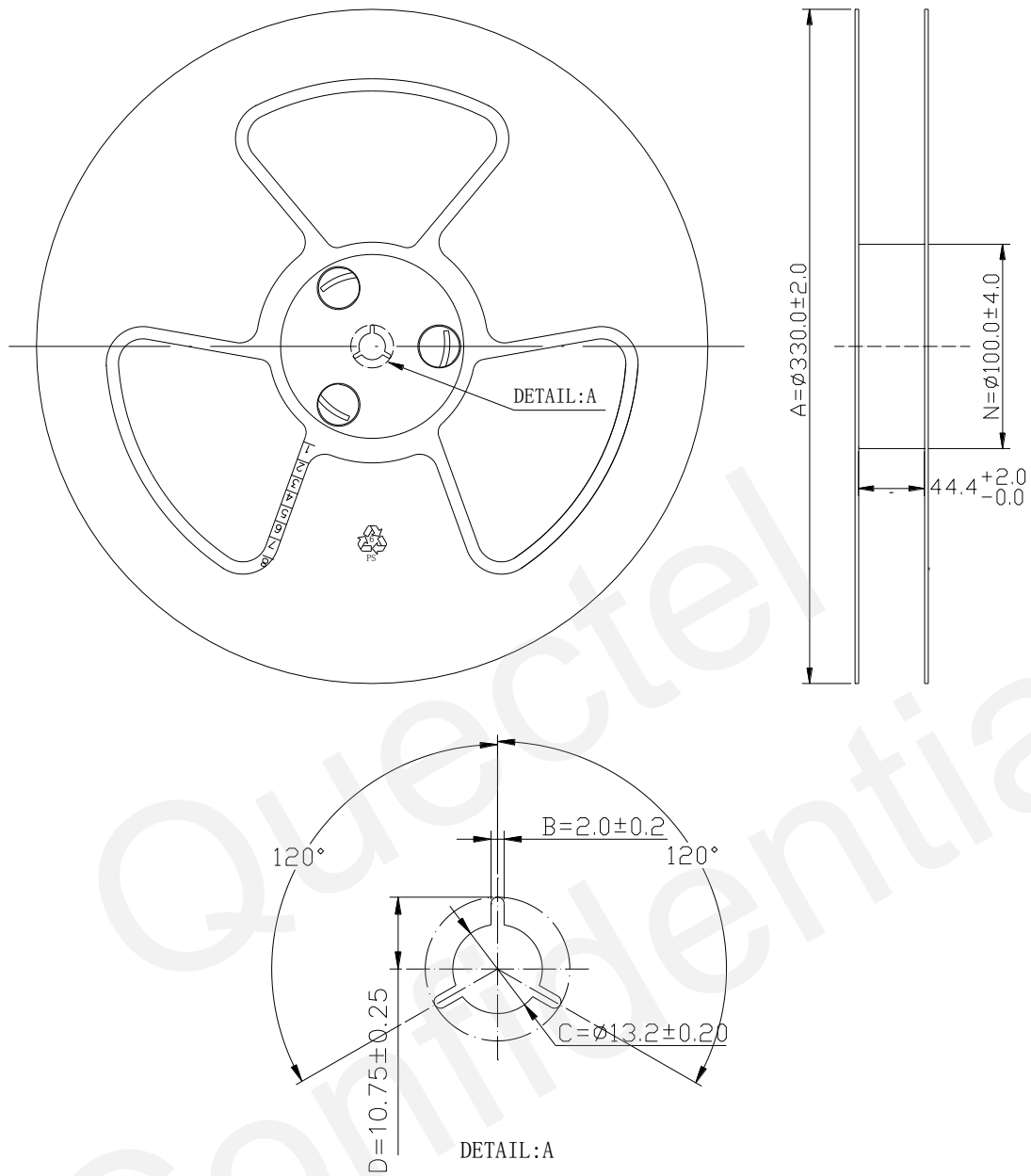


Figure 39: Dimensions of Reel

Table 23: Reel Packing

Model Name	MOQ for MP	Minimum Package: 250pcs	Minimum Package×4=1000pcs
M72	250pcs	Size: 370 × 350 × 56mm N.W: 1.08kg G.W: 1.94kg	Size: 380 × 250 × 365mm N.W: 4.30kg G.W: 7.98kg

# 8 Appendix A Reference

**Table 24: Related Documents**

SN	Document Name	Remark
[1]	Quectel_M72_AT_Commands_Manual	AT commands manual
[2]	GSM_UART_Application_Note	UART port application note
[3]	Module_Secondary_SMT_User_Guide	Module secondary SMT user guide
[4]	GSM_EVB_User_Guide	GSM EVB user guide
[5]	Quectel_GSM_Module_Digital_IO_Application_Note	GSM module digital IO application note
[6]	ITU-T Draft new recommendation V.25ter	Serial asynchronous automatic dialing and control
[7]	GSM 07.07	Digital cellular telecommunications (Phase 2+); AT command set for GSM Mobile Equipment (ME)
[8]	GSM 07.10	Support GSM 07.10 multiplexing protocol
[9]	GSM 07.05	Digital cellular telecommunications (Phase 2+); Use of Data Terminal Equipment – Data Circuit terminating Equipment (DTE – DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS)
[10]	GSM 11.14	Digital cellular telecommunications (Phase 2+); Specification of the SIM Application Toolkit for the Subscriber Identity module – Mobile Equipment (SIM – ME) interface
[11]	GSM 11.11	Digital cellular telecommunications (Phase 2+); Specification of the Subscriber Identity module – Mobile Equipment (SIM – ME) interface
[12]	GSM 03.38	Digital cellular telecommunications (Phase 2+); Alphabets and language-specific information

[13] GSM 11.10

Digital cellular telecommunications (Phase 2); Mobile Station (MS) conformance specification; Part 1: Conformance specification

**Table 25: Terms and Abbreviations**

Abbreviation	Description
ADC	Analog-to-Digital Converter
AMR	Adaptive Multi-Rate
ARP	Antenna Reference Point
ASIC	Application Specific Integrated Circuit
BER	Bit Error Rate
BOM	Bill of Material
BTS	Base Transceiver Station
CHAP	Challenge Handshake Authentication Protocol
CS	Coding Scheme
CTS	Clear To Send
DAC	Digital-to-Analog Converter
DRX	Discontinuous Reception
DSP	Digital Signal Processor
DCE	Data Communications Equipment (typically module)
DTE	Data Terminal Equipment (typically computer, external controller)
DTR	Data Terminal Ready
DTX	Discontinuous Transmission
EFR	Enhanced Full Rate
EGSM	Enhanced GSM
EMC	Electromagnetic Compatibility

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ESD	Electrostatic Discharge
ETS	European Telecommunication Standard
FCC	Federal Communications Commission (U.S.)
FDMA	Frequency Division Multiple Access
FR	Full Rate
GMSK	Gaussian Minimum Shift Keying
GPRS	General Packet Radio Service
GSM	Global System for Mobile Communications
HR	Half Rate
I/O	Input/Output
IC	Integrated Circuit
IMEI	International Mobile Equipment Identity
Imax	Maximum Load Current
Inorm	Normal Current
kbps	Kilo Bits Per Second
LED	Light Emitting Diode
MO	Mobile Originated
MS	Mobile Station (GSM engine)
MT	Mobile Terminated
PAP	Password Authentication Protocol
PBCCH	Packet Switched Broadcast Control Channel
PCB	Printed Circuit Board
PDU	Protocol Data Unit
PPP	Point-to-Point Protocol
RF	Radio Frequency

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RMS	Root Mean Square (value)
RTC	Real Time Clock
RX	Receive Direction
SIM	Subscriber Identification Module
SMS	Short Message Service
TDMA	Time Division Multiple Access
TE	Terminal Equipment
TX	Transmitting Direction
UART	Universal Asynchronous Receiver & Transmitter
URC	Unsolicited Result Code
USSD	Unstructured Supplementary Service Data
VSWR	Voltage Standing Wave Ratio
Vmax	Maximum Voltage Value
Vnorm	Normal Voltage Value
Vmin	Minimum Voltage Value
VIHmax	Maximum Input High Level Voltage Value
VIHmin	Minimum Input High Level Voltage Value
VILmax	Maximum Input Low Level Voltage Value
VILmin	Minimum Input Low Level Voltage Value
VImax	Absolute Maximum Input Voltage Value
VImin	Absolute Minimum Input Voltage Value
VOHmax	Maximum Output High Level Voltage Value
VOHmin	Minimum Output High Level Voltage Value
VOLmax	Maximum Output Low Level Voltage Value
VOLmin	Minimum Output Low Level Voltage Value

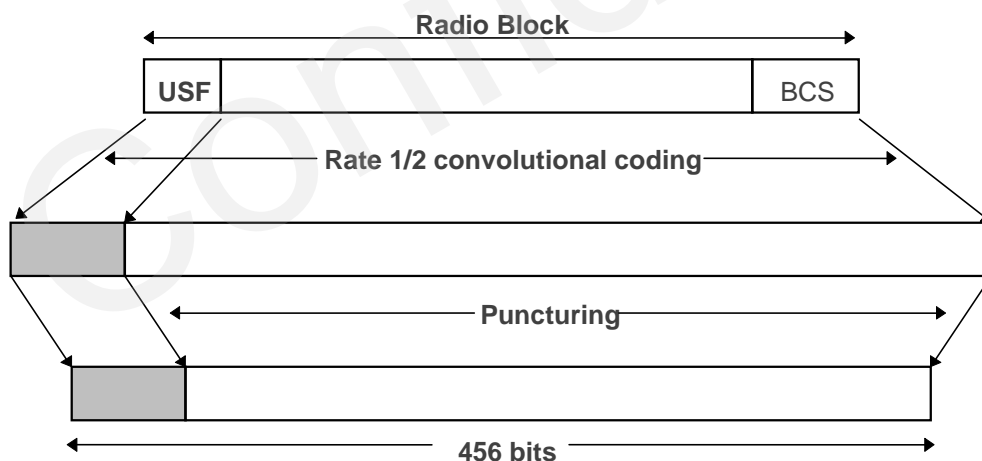
# 9 Appendix B GPRS Coding Scheme

Four coding schemes are used in GPRS protocol. The differences between them are shown in the following table.

**Table 26: Description of Different Coding Schemes**

Scheme	Code Rate	USF	Pre-coded USF	Radio Block excl.USF and BCS	BCS	Tail	Coded Bits	Punctured Bits	Data Rate Kb/s
CS-1	1/2	3	3	181	40	4	456	0	9.05
CS-2	2/3	3	6	268	16	4	588	132	13.4
CS-3	3/4	3	6	312	16	4	676	220	15.6
CS-4	1	3	12	428	16	-	456	-	21.4

Radio block structure of CS-1, CS-2 and CS-3 is shown as the figure below.



**Figure 40: Radio Block Structure of CS-1, CS-2 and CS-3**



Radio block structure of CS-4 is shown as the following figure.

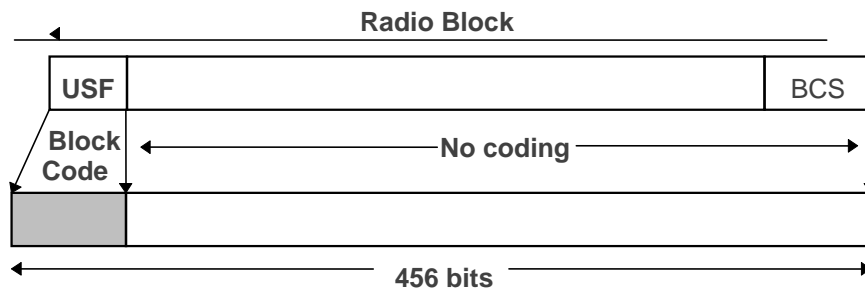


Figure 41: Radio Block Structure of CS-4

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# 10 Appendix C GPRS Multi-slot Class

Twenty-nine classes of GPRS multi-slot modes are defined for MS in GPRS specification. Multi-slot classes are product dependant, and determine the maximum achievable data rates in both the uplink and downlink directions. Written as 3+1 or 2+2, the first number indicates the amount of downlink timeslots, while the second number indicates the amount of uplink timeslots. The active slots determine the total number of slots the GPRS device can use simultaneously for both uplink and downlink communications. The description of different multi-slot classes is shown in the following table.

**Table 27: GPRS Multi-slot Classes**

Multislot Class	Downlink Slots	Uplink Slots	Active Slots
1	1	1	2
2	2	1	3
3	2	2	3
4	3	1	4
5	2	2	4
6	3	2	4
7	3	3	4
8	4	1	5
9	3	2	5
10	4	2	5
11	4	3	5
12	4	4	5